SPEAr320S

Embedded MPU with ARM926 core for industrial and consumer applications

Datasheet – production data

Features

- ARM926EJ-S CPU core, up to 333 MHz
- Multilayer bus matrix, up to 166 MHz
- Internal memories: 32 KB ROM, 8 KB SRAM
- Memory interfaces:
  - DDR controller (DDR2-666, LPDDR-333), 8-/16-bit
  - Serial NOR Flash controller
  - Parallel NAND Flash controller, 8-/16-bit data bus
  - Parallel NOR Flash/FPGA interface, 8-/16-bit data bus
- Connectivity:
  - 2 x USB 2.0 Host ports (integrated PHY)
  - 1 x USB 2.0 Device port (integrated PHY)
  - 2 x Fast Ethernet ports (external MII/RMII PHY)
  - 1 x MMC-SD card/SDIO controller
  - 2 x CAN 2.0 ports
  - 7 x UART ports
  - 3 x I2C ports: master/slave
  - 3 x synchronous serial ports, SPI/Microwire/TI protocols, master/slave
  - 1 x RS485 interface
  - 1 x fast IrDA interface
  - 1 x legacy parallel port (IEEE 1284), slave mode
  - 10-bit ADC, 8 channels, 1 Msps
  - Up to 102 GPIOs with interrupt capability
- HMI support:
  - LCD display controller, up to XGA (1024 x 768, 24 bpp)
  - Resistive touchscreen interface
  - JPEG codec accelerator
  - 1 x I2S digital audio port
- Security
  - Cryptographic co-processor

LFBGA289 (15 x 15 x 1.7 mm)

- Miscellaneous functions:
  - System controller, vectored interrupt controller, watchdog, real-time clock
  - Dynamic power-saving features
  - 8-channel DMA controller
  - 6 x 16-bit general purpose timers with prescaler and 4 capture inputs
  - 4 x PWM generators
  - Debug and trace interfaces: JTAG/ETM

Applications

The SPEAr320S embedded MPU is configurable for a range of industrial and consumer applications such as:

- Human machine interface (HMI) terminals
- Factory automation / PLCs
- Medical equipment
- Smart energy meters and gateways
- VoIP phones
- Small printers

The device is hardware-compliant to the support of both real-time (RTOS) and high-level (HLOS) operating systems, such as Linux and Windows Embedded Compact 7.

Table 1. Device summary

Order code	Temp range, °C	Package	Packing
SPEAR320S-2	-40 to 85	LFBGA289 (15x15 mm, pitch 0.8 mm)	Tray

This is information on a product in full production. www.st.com

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1 Description

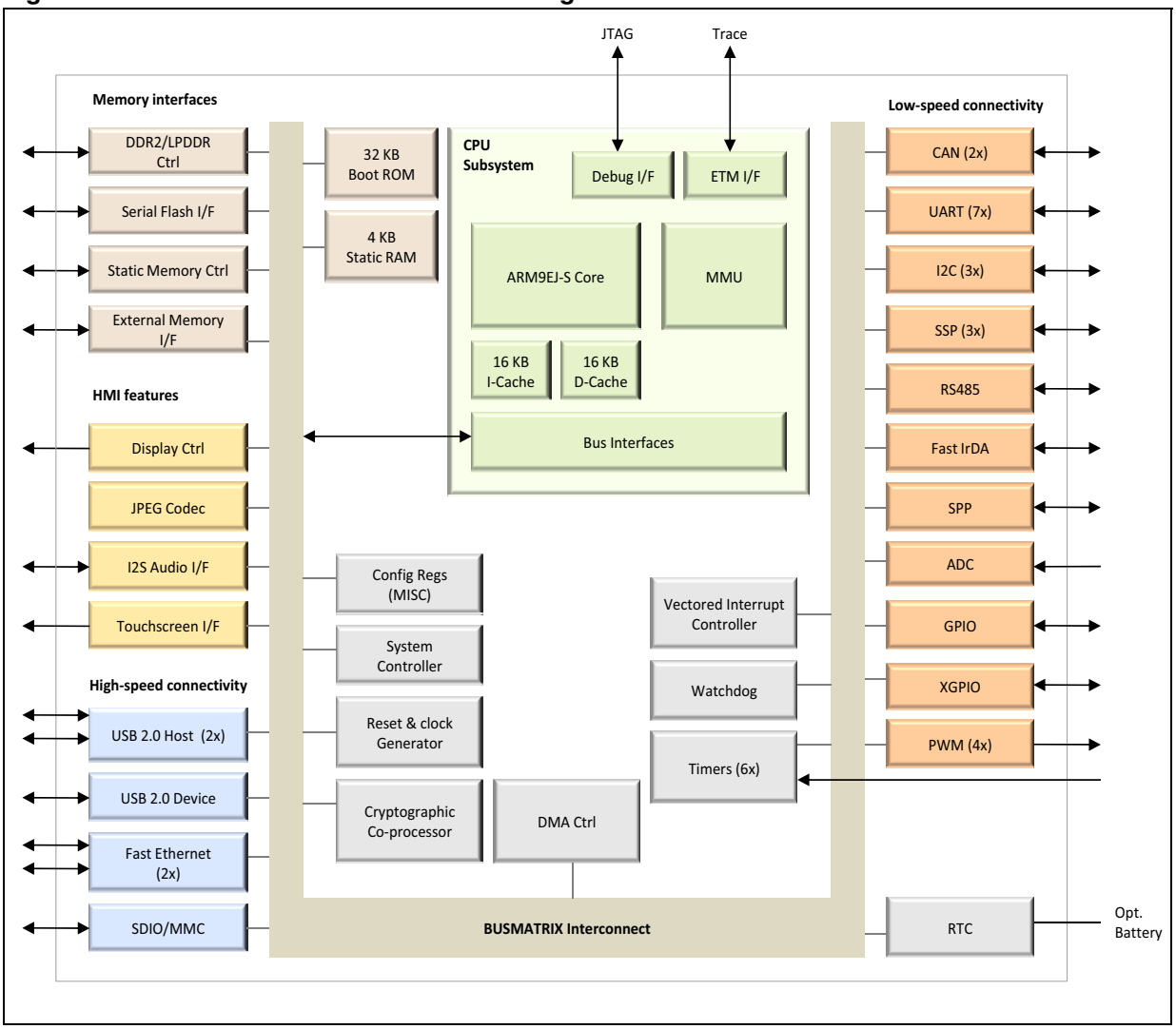
SPEAr320S is a member of the SPEAr family of embedded MPUs and is optimized for industrial automation and consumer markets. The device is based on the ARM926EJ-S processor (up to 333 MHz), widely used in applications where the processing performance is required to be higher than the one achievable with microcontrollers.

SPEAr320S provides an integrated MMU (memory management unit) which enables to support high-level operating systems (HLLs), such as Linux and Windows Embedded Compact 7. In addition, a rich set of integrated peripherals (memory interfaces, connectivity, HMI, cryptography) allows the device to be used in a wide range of embedded applications.

The SPEAr320S architecture is based on multiple functional blocks interacting through a multilayer interconnection bus matrix. The switch matrix structure allows different subsystem data flows to be executed in parallel improving the core platform efficiency. High performance master agents are directly interconnected with the memory controller reducing the memory access latency. The overall memory bandwidth assigned to each master port can be programmed and optimized through an internal efficient weighted round-robin arbitration mechanism.

The SPEAr320S device is fully backward-compatible with the previous SPEAr320 product at both hardware and software programming levels. The extended functionality is achieved by enhanced I/O multiplexing, preserving the same pinout and ball map, as well as by a new software-definable configuration mode.

Figure 1. SPEAr320S architectural block diagram



2 Device functions

2.1 CPU subsystem

The core of the SPEAr320S is an ARM926EJ-S reduced instruction set computer (RISC) processor.

Main features:

- Supports the 32-bit ARM and 16-bit Thumb instruction sets, enabling the user to trade off between high performance and high code density. It also includes features for efficient execution of Java byte codes.
- The ARM CPU can be clocked at a frequency up to 333 MHz and includes both an instruction (16 KB) and a data cache (16 KB). In addition to the capability of running any real-time operating system (RTOS) available for ARM9 processors, the ARM926EJ-S subsystem also provides a memory management unit (MMU) that enables to support high-level operating systems (HLLs) like Linux and Windows Embedded Compact 7.
- Includes an embedded trace module (ETM Medium+) for real-time CPU activity tracing and debugging. It supports 4-bit and 8-bit normal trace mode and 4-bit demultiplexed trace mode, with normal or half-rate clock.

For detailed information, please refer to the following public documents available from the ARM Ltd. website:

- *CPU Core:*

  ARM9EJ-S, Technical Reference Manual, Revision: r1p2

  http://infocenter.arm.com/help/topic/com.arm.doc.ddi0222b/DDI0222.pdf
- *CPU Subsystem:*

  ARM926EJ-S, Technical Reference Manual, Revision: r0p5

  http://infocenter.arm.com/help/topic/com.arm.doc.ddi0198e/DDI0198E_arm926ejs_r0p5_trm.pdf

2.2 Internal memories (BootROM/SRAM)

SPEAr320S integrates two embedded memories:

- 32 KB ROM (BootROM), storing a factory-defined device bootstrap firmware.
- 8 KB Static RAM (SRAM), partly used by bootstrap firmware, but also available as general-purpose memory after system startup.

The firmware in BootROM is automatically executed after SPEAr320S reset and supports the following bootstrap modes:

- Boot from serial NOR Flash
- Boot from parallel NAND Flash
- Boot from parallel NOR Flash
- Boot from USB Device port

The BootROM firmware selects the boot mode from the boot pin settings (see *Section 3.4.4: Boot pins*). A setting is also available to allow the BootROM execution to be bypassed.

The first three modes support alternate ways of locating and starting the selected operating system or target custom software. Such modes require a second-level boot firmware to be stored in external Flash memory. A reference code for such boot loader (called “XLoader”) is provided by STMicroelectronics in source and binary formats for the SPEAr320S evaluation boards. Such code must be adapted according to the specific DDR memory components found on target customer systems.

The fourth mode can be used for installing and updating the software on external Flash memories through a PC-based software utility provided by STMicroelectronics exploiting a USB link between a PC and a target SPEAr320S board.

2.3 Multiport DDR controller (MPMC)

SPEAr320S integrates a high-performance controller able to manage DDR2 (double data rate) and LPDDR (low power DDR) external dynamic memory devices.

Main features:

- Support for DDR2 up to 333 MHz (666 MT/sec)
- Support for LPDDR up to 166 MHz (333 MT/sec)
- Support for 8-/16-bit external data bus
- Support for up to 1 GByte DDR2/LPDDR memory address space
- Full initialization of memories on controller reset
- 6 independent internal ports: five of them are used to access the external memory while one is reserved for programming the controller configuration registers
- Programmable built-in port arbitration scheme to ensure high memory bandwidth utilization
- Fully pipelined read and write commands
- Self-refresh mode for power saving
- Integrated physical layer (PHY) and delay locked loops (DLLs) for fine tuning of the timing parameters, maximizing the data valid windows at different frequencies

2.4 Serial NOR Flash controller (SMI)

SPEAr320S integrates a Flash memory controller able to manage serial, SPI-compatible, NOR Flash and EEPROM external memory devices.

Main features:

- Support for up to 32 MByte external serial memory storage capacity (2 x 16 MB addressable banks by independent chip select signals)
- SMI clock up to 50 MHz (fast read mode) or 20 MHz (normal mode), with software configurable 7-bit prescaler

The bootstrap requires that the external serial Flash is located at bank 0 (enabled after power-on reset). During the boot phase, a sequence of instructions is automatically sent to bank 0. Refer to SPEAr320S reference manuals for more details.

The BootROM firmware has been tested with the following external serial memory components:

- Micron M25P and M45P families (SPI Flash)
- Micron M95 family (SPI EEPROM), except for M95040, M95020 and M95010
- ATMEL AT25F family (SPI Flash)
- YMC Y25F family (SPI Flash)
- Microchip/SST SST25LF family (SPI Flash)

2.5 Parallel NAND Flash controller (FSMC)

SPEAr320S integrates a flexible static memory controller able to manage external parallel NAND Flash memories.

Main features:

- 8-/16-bit external data bus; 16-bit only supported when Mode 3 (expanded automation mode) chip configuration is selected by software.
- Support for up to 4 memory banks
- Independent timing configuration and chip select signal for each memory bank
- Fully programmable timings:
  - wait states (up to 31)
  - bus turnaround cycles (up to 15)
  - output enable and write enable delays (up to 15)
- External asynchronous wait control
- Internal AHB bus burst transfer support to reduce Flash memory access time

The BootROM firmware directly supports the external NAND Flash components shown in *Table 2*.

Table 2. NAND Flash devices supported by the BootROM firmware

Part number	Vendor	Density	Capacity	Bus width	Page size
K9F1208V0A	Samsung	64 Mb	8 MB	x8	512 + 16 bytes
NAND128W3A28N6	Micron	128 Mb	16 MB	x8	512 + 16 bytes
NAND256W3A2BN6	Micron	256 Mb	32 MB	x8	512 + 16 bytes
KM29U256	Samsung	256 Mb	32 MB	x8	512 + 16 bytes
NAND512W3A2C2A6	Micron	512 Mb	64 MB	x8	512 + 16 bytes
NAND01GW3B2BN6	Micron	1 Gb	128 MB	x8	2048 + 64 bytes
NAND01GW4B2AN6	Micron	1 Gb	128 MB	x16	1024 words + 32 bytes
K9F1G16U0M	Samsung	1 Gb	128 MB	x16	1024 words + 32 bytes
NAND01GR3B	Micron	1 Gb	128 MB	x8	2048 + 64 bytes
NAND02GW3B2CN6	Micron	2 Gb	256 MB	x8	2048 + 64 bytes
NAND02GW3A	Micron	2 Gb	256 MB	x8	2048 + 64 bytes

Table 2. NAND Flash devices supported by the BootROM firmware (continued)

Part number	Vendor	Density	Capacity	Bus width	Page size
K9F2G08V0A	Samsung	2 Gb	256 MB	x8	512 + 16 bytes
NAND04GW3B2BN6	Micron	4 Gb	512 MB	x8	2048 + 64 bytes
K9F4G08V0A	Samsung	4 Gb	512 MB	x8	512 + 16 bytes
NAND08GW3B2CN6	Micron	8 Gb	1 GB	x8	2048 + 64 bytes
K9K8G08V0A	Samsung	8 Gb	1 GB	x8	512 + 16 bytes
K9F8G08V0M	Samsung	8 Gb	1 GB	x8	512 + 16 bytes

2.6 External memory interface (EMI)

SPEAr320S integrates an additional external memory interface that can be used to manage external parallel NOR Flash memories as well as FPGA devices. This interface is available only when Mode 3 (expanded automation mode) chip configuration is selected by software.

Main features:

- 24-bit address bus
- 16-bit data bus
- 4 chip select signals
- Support for single asynchronous transfers
- Support for peripherals using Byte Lane procedure

The external Flash component must be in read mode at reset. Usually, this is true for most parallel NOR devices.

2.7 USB 2.0 Host ports (UHC)

SPEAr320S provides two USB 2.0 Host ports with integrated PHYs.

Main features:

- Each port can be independently configured for high-speed mode (USB 2.0, up to 480 Mbps); in this case, the corresponding controller is programmed according to standard EHCI specifications.
- Each port can be independently configured for full-speed mode (USB 1.1, up to 12 Mbps) or low-speed mode (USB 1.1, up to 1.5 Mbps); in this case, the corresponding controller is programmed according to standard OHCI specifications.
- Internal 2 KB FIFO queues
- Internal DMA support
- Dedicated output control signals to manage external power switches
- Dedicated input signals to sense any over-current condition detected by external power switches

2.8 USB 2.0 Device port (UDC)

SPEAr320S provides a USB 2.0 Device port with integrated PHY.

Main features:

- Support for all standard modes:
  - high-speed mode (USB 2.0, up to 480 Mbps)
  - full-speed mode (USB 1.1, up to 12 Mbps)
  - low-speed mode (USB 1.1, up to 1.5 Mbps)
- Up to 16 physical endpoints, configurable as different logical endpoints
- Internal 4 KB FIFO queue (shared among all the endpoints)
- DMA mode, with descriptor-based structures in application memory
- Slave-only mode
- Support for 8-, 16- and 32-bit wide data transactions on the internal bus
- Support for USB plug detection (UPD)

2.9 Fast Ethernet ports (MII/RMII)

SPEAr320S features three multiplexed Ethernet MACs, supporting up to two ports concurrently.

The three controllers are named:

- MII0
- RMII0
- MII1/RMII1

2.9.1 MII0 Ethernet controller

Main features:

- Media independent interface (MII) to an external PHY as defined in the IEEE 802.3u specification
- Support for 10 and 100 Mbps data transfer rates
- Support for both full-duplex and half-duplex (CSMA/CD protocol) operating modes
- Integrated FIFO queues (4 KB RX, 2 KB TX)
- Native DMA with single-channel transmit and receive engines, providing 32-/64-/128-bit data transfers; DMA provides ring-buffer or linked-list descriptor options.
- Programmable Ethernet frame length to support both standard and jumbo frames (with size up to 16 KB)
- Flexible address filtering modes
- Statistics counter registers for RMON/MIB
- Support for 802.1Q VLAN tagging
- Wake-on-LAN support
- Automatic padding and CRC generation on transmitted frames

2.9.2 RMII0 and MII1/RMII1 Ethernet controllers

These functional blocks extend Ethernet capability by covering the Media independent interface (MII) and Reduced media independent interface (RMII) standards.

They can be used in two ways:

- as a single additional MAC controller with Media independent interface (MII1)
- as two MAC controllers with Reduced media independent interface (RMII0, RMII1)

In *RMII configuration*, each controller has an independent set of data and control lines. The reference clock (50 MHz) is shared by the controllers.

Main features:

- Compatible with IEEE Standard 802.3
- UNH tested
- 10 and 100 Mbit/s operation
- Full and half duplex operation
- Statistics counter registers for RMON/MIB
- Automatic pad and CRC generation on transmitted frames
- Automatic discard of frames received with errors
- Address checking logic supports up to four specific 48-bit addresses
- Supports promiscuous mode where all valid received frames are copied to memory
- Hash matching of unicast and multicast destination addresses
- External address matching of received frames
- Supports serial network interface operation
- Half-duplex flow control by forcing collisions on incoming frames
- Full-duplex flow control with recognition of incoming pause frames and hardware generation of transmitted pause frames
- Support for 802.1Q VLAN tagging with recognition of incoming VLAN and priority tagged frames
- Multiple buffers per receive and transmit frame
- Jumbo frames of up to 10240 bytes supported

2.10 MMC-SD card/SDIO controller

The MMC-SD card /SDIO controller conforms to the SD Host Controller Standard Specification, version 2.0. It handles SD/SDIO protocol at transmission level by packing data, adding cyclic redundancy check (CRC) and start/end bit as well as checking for transaction format correctness.

The controller is designed to work with I/O cards, read-only cards and read/write cards, and can operate either in SD mode (1-bit, 4-bit, 8-bit) or in SPI mode.

The interface is compliant to the following standards:

- SD Host Controller Standard Specification, version 2.0
- SDIO Card Specification, version 2.0
- SD Memory Card Specification Draft, version 2.0
- SD Memory Card Security Specification, version 1.01
- MMC Specification, version 3.31 and 4.2

Main features:

- Up to 100 Mbps data rate using 4 parallel data lines (SD4 bit mode)
- Up to 416 Mbps data rate using 8-bit parallel data lines (SD8 bit mode)
- DMA-based and non-DMA modes of operation
- Support for MMC Plus and MMC Mobile
- Card detection (insertion / removal)
- Card password protection
- Host clock rate variable between 0 and 48 MHz
- Multimedia card interrupt mode
- Cyclic redundancy check: CRC7 (command) and CRC16 (data integrity)
- Error correction code (ECC) support for MMC4.2 cards
- Supports for Read Wait Control and Suspend/Resume
- FIFO overrun and under-run handling by stopping SD clock

2.11 CAN 2.0 ports

SPEAr320S provides two independent CAN (controller area network) bus ports, typically used in automotive, industrial and medical applications. For the connection to the physical layer, an additional transceiver per port is required.

For communication on a CAN network, the controller enables to configure individual message objects. The message objects and identifier masks for acceptance filtering of received messages are stored in an integrated message RAM. All functions concerning the handling of messages are implemented by a message handler. Those functions are the acceptance filtering, the transfer of messages between the CAN core and the message RAM, the handling of transmission requests as well as the generation of interrupts.

Main features:

- Support for CAN protocol, version 2.0 part A and B
- Transfer rate up to 1 Mbps
- Internal RAM storage for up to 16 message objects (16 x 136 bytes memory)
- Identifier mask per message object
- Maskable interrupts
- Programmable loop-back mode for self-test operation
- Disabled automatic retransmission mode for time triggered CAN applications

2.12 Asynchronous serial ports (UART)

The SPEAr320S has 7 UART ports. The actual number of concurrently exploitable ports depends on the selected chip operating mode. The different capabilities of each port are summarized in *Table 3* below.

Table 3. SPEAr320S UART capabilities

Port	Speed	Hardware flow control	Modem signals
UART0	Up to 3 Mbps	Yes	Yes (as alternate function)
UART1	Up to 7 Mbps	Yes (except for Mode 1 and 2)	Yes (except for Mode 1 and 2)
UART2 - 6	Up to 7 Mbps	No	No

Main features:

- Programmable baud rate generator
- Transmit FIFO queue (8-bit data, 16 entries) and receive FIFO queue (12-bit data/status, 16 entries) with disabling option (1-byte buffer depth)
- Supports for DMA operation
- Hardware flow control (RTS,CTS) for some ports and configurations
- Modem control signals (DCD, DSR, DTS, RI) for some ports and configurations
- Fully programmable serial interface with following parameters:
  - data bits: 5, 6, 7 or 8
  - parity: even, odd, stick or none (generation and detection)
  - stop bits: 1 or 2
  - line break handling (generation and detection)
- Flexible interrupt handing and masking

2.13 I2C bus ports (I2C)

The SPEAr320S provides three independent I2C bus ports. Each port can be configured as I2C bus master or slave.

Main features:

- Compliant to the I2C bus specification (Philips)
- Support for the 3 standard speeds:
  - Standard (100 Kbps)
  - Fast (400 kbps)
  - High-speed
- Support for direct memory access (DMA)
- Clock synchronization
- Multimaster mode (bus arbitration)
- 7-bit or 10-bit addressing
- 7-bit or 10-bit combined format transfers
- Slave bulk transfer mode
- Transmit and receive buffers
- Interrupt or polled-mode operation
- Handling of bit and byte waiting at all bus speeds
- Digital filter for the received SDA and SCL lines
- Filtering out of legacy CBUS addresses

2.14 Synchronous serial ports (SSP)

SPEAr320S provides three independent synchronous serial ports. Each port can be configured as master or slave.

Main features:

- Support for the following protocols:
  - SPI (Motorola)
  - Microwire (National Semiconductor)
  - SSI (Texas Instruments)
- Programmable parameters:
  - Clock bit rate and prescale
  - Data frame size (from 4 to 16 bits)
- Separate transmit and receive FIFO queues (8 x 16-bit entries)
- Independent masking of transmit FIFO, receive FIFO, and receive overrun interrupts
- Internal loopback test mode available
- DMA interface

2.15 RS485 port (RS485)

SPEAr320S provides an additional UART port specialized for the RS485 standard.

Main features:

- Transmit FIFO queue (8-bit data, 16 entries) and receive FIFO queue (12-bit data/status, 16 entries) with disabling option (1-byte buffer depth)
- Speed up to 7 Mbps

2.16 Fast infrared port (IrDA)

SPEAr320S provides an infrared interface compliant to the IrDA (Infrared Data Association) standard specification. An external infrared transceiver is assumed. The Fast IrDa controller performs the modulation and demodulation of the infrared signals as well as the wrapping of IrDA link access protocol (IrLAP) frames.

Main features:

- Support for the following standards:
  - IrDA serial infrared physical layer specification (IrPHY), version 1.3
  - IrDA link access protocol (IrLAP), version 1.1
- Support for the following modes and baud rates:
  - Serial infrared (SIR): 9.6 Kbps, 19.2 Kbps, 38.4 Kbps, 57.6 Kbps, 115.2 Kbps
  - Medium infrared (MIR): 576 Kbps, 1152 Kbps
  - Fast infrared (FIR): 4 Mbps
- Support for half-duplex infrared frame transmission and reception
- Interface compliant to all IrDA transceivers with configurable polarity of TX and RX signals
- Integrated CRC algorithm: 16-bit (SIR, MIR), 32-bit (FIR)
- Automatic generation of preamble, start and stop flags
- RZI (return-to-zero inverted) modulation/demodulation scheme for SIR and MIR modes
- 4PPM (4-pulse position modulation) modulation/demodulation scheme for FIR mode
- Synchronization by DPLL in FIR mode
- Payload data transfer controllable by either CPU or DMA controller
- Two clock domains:
  - Dedicated clock (IRDA_CLK signal) for accurate signal generation (48 MHz)
  - Independent and variable clock for the bus interface (13 MHz)

2.17 Legacy IEEE 1284 parallel port (SPP)

SPEAr320S provides a parallel port (slave mode only) compliant to the legacy IEEE 1284 standard.

Main features:

- Unidirectional 8-bit data transfer from SPEAr320S slave to external host
- Additional 9th bit for parity/data/command
- Maskable interrupts for data, device reset, auto line feed

2.18 A/D converter (ADC)

SPEAr320S provides an integrated analog-to-digital converter.

Main features:

- Successive approximation conversion method
- 8 x analog input channels, ranging from 0 to 2.5 V
- 10-bit resolution
- Sampling rate up to 1 Msamples/s
- Support for 13.5-bit resolution at 8 Ksamples/s by oversampling and accumulation
- INL ± 1 LSB, DNL ± 1 LSB
- Programmable conversion speed (minimum conversion time is 1 µs)
- Programmable averaging of multiple values from 1 (no averaging) up to 128
- Programmable auto scan for all the 8 channels

2.19 General purpose I/Os (GPIO/XGPIO)

Up to 102 GPIOs are available in SPEAr320S when some embedded IPs are not needed in the customer application (see *Section 3.4: Shared IO pins (PL_GPIOs)*).

SPEAr320S provides two mechanisms:

- a basic GPIO module (called “basGPIO”): this functional block provides 6 pins, each one programmable by software with the following features:
  - direction: input (default at reset) or output
  - interrupt triggering mode
- the possibility to configure and use any PL_GPIO pin as alternative to the corresponding predefined signal purpose (called extended GPIO or “XGPIO”). XGPIOs have the same capability of basic GPIOs, while the register programming model is different.

2.20 LCD display controller (CLCD)

SPEAr320S has an integrated display controller able to directly interface a variety of color and monochrome LCD panels.

Main features:

- Programmable resolution up to 1024 x 768 (XGA)
- Programmable timing parameters
- Support for TFT (thin film transistor) color displays
- Supports for STN (super twisted nematic) displays (single and dual panel) with 4- or 8-bit interfaces
- AC bias signal for STN and data enable signal for TFT panels
- Gray scaling algorithm

The set of supported pixel widths and formats for each display type is shown in *Table 4*.

Table 4. Pixel widths and formats available for different display types

Display	1 bpp	2 bpp	4 bpp	8 bpp	16 bpp	24 bpp
Color TFT	Palette of 2 colors over 64K	Palette of 4 colors over 64K	Palette of 16 colors over 64K	Palette of 256 colors over 64K	RGB 5:5:5 + intensity (64K colors)	RGB 8:8:8 (16M colors)
Color STN	Palette of 2 colors over 3375	Palette of 4 colors over 3375	Palette of 16 colors over 3375	Palette of 256 colors over 3375	RGB 4:4:4 (4096 colors)	-
Mono STN	Palette of 2 gray levels over 15	Palette of 4 gray levels over 15	Palette of 16 gray levels over 15	Palette of 256 colors over 3375	-	-

2.21 Touchscreen interface (OUT_X)

SPEAr320S provides a toggling output signal (OUT_X) that can be connected to an external touchscreen panel. This interface operates in combination with the A/D converter (ADC). Two coordinates can be read by software from the ADC: one at the end of the high period and one at the end of the low period of OUT_X signal.

2.22 JPEG codec accelerator (JPGC)

SPEAr320S provides an integrated hardware accelerator for decoding and encoding standard JPEG images.

JPEG data streams to be decoded must be compliant with the interchange format syntax specified in the ISO/IEC 10918-1. The JFIF image file format is also supported through header processing.

The output format for decoding (and input format for encoding) is a MCU stream, not a conventional bitmap format like RGB. Displaying a decoded JPEG still picture would require further steps and algorithms like color space conversion and scaling.

Main features:

- Compliance with the baseline JPEG standard (ISO/IEC 10918-1)
- Single-clock per pixel encoding/decoding
- Support for up to four channels of component color
- 8-bit/channel pixel depths
- Programmable quantization tables (up to four)
- Programmable Huffman tables (two AC and two DC)
- Programmable minimum coded unit (MCU)
- Configurable JPEG header processing
- Support for restart marker insertion
- Use of two DMA channels and two 8 x 32-bit FIFOs (local to the JPEG) for efficient transferring and buffering of encoded/decoded data from/to the Codec core.

2.23 Digital audio port (I2S)

The SPEAr320S integrates a digital audio port compliant to standard I2S (Philips) specifications.

Main features:

- I2S master mode
- Stereo (2.0) playback and recording
- Support for standard sampling rates (8, 16, 32, 44.1, 48, 96, 192 kHz); the clock input is 24 MHz, so the rate precision depends on the chosen rate and divider.
- Support of a range of audio samples: 12 / 16 / 20 / 24/ 32 bits
- Programmable thresholds for internal FIFO queues
- Capability of using DMA transfer

2.24 Cryptographic co-processor (C3)

SPEAr320S provides an embedded cryptographic co-processor (C3). C3 is a high-performance instruction-driven DMA-based engine that can be used to accelerate the processing of security algorithms.

After its initial configuration by the main CPU, it runs in a completely autonomous way (DMA data in, data processing, DMA data out), until the completion of all the requested operations. C3 firmware is fetched from system memory.

Main features:

- Supported cryptographic algorithms:
  - Advanced encryption standard (AES) cipher in ECB, CBC, CTR modes
  - Data encryption standard (DES) cipher in ECB and CBC modes
  - SHA-1, HMAC-SHA-1, MD5, HMAC-MD5 digests
- Hardware chaining of cryptographic stages for optimized data flow when multiple algorithms are required to process the same set of data (for example, encryption and hashing on the fly)

2.25 System controller (SYSCTR)

The system controller provides an interface for controlling the operation of the overall system.

Main features:

- Power saving system mode control
- Crystal oscillator and PLL control
- Configuration of system response to interrupts
- Reset status capture and soft reset generation
- Watchdog and timer module clock enable

Using three mode control bits, the system controller switches the SPEAr320S to any of the four different modes: DOZE, SLEEP, SLOW and NORMAL.

- **SLEEP mode**: in this mode, the system clocks, HCLK and CLK, are disabled and the system controller clock, SCLK, is driven by a low-speed oscillator (nominally 32768 Hz). When either a FIQ or an IRQ interrupt is generated (through the VIC), the system enters DOZE mode. Additionally, the operating mode setting in the system control register automatically changes from SLEEP to DOZE.
- **DOZE mode**: in this mode, the system clocks, HCLK and CLK, and the system controller clock are driven by a low-speed oscillator. The system controller moves into SLEEP mode from DOZE mode only when none of the mode control bits are set and the processor is in wait-for-interrupt state. If SLOW mode or NORMAL mode is required, the system moves into the XTAL control transition state to initialize the crystal oscillator.
- **SLOW mode**: during this mode, both the system clocks and the system controller clock are driven by the crystal oscillator. If NORMAL mode is selected, the system goes into the “PLL control” transition state. If neither the SLOW nor the NORMAL mode control bits are set, the system goes into the “Switch from XTAL” transition state.
- **NORMAL mode**: in NORMAL mode, both the system clocks and the system controller clock are driven by the PLL output. If the NORMAL mode control bit is not set, then the system goes into the “Switch from PLL” transition state.

2.25.1 Reset and clock generator

The reset and clock generator is a fully programmable block that generates all the clocks necessary to the chip.

The default operating clock frequencies are:

- Clock @ 333 MHz for the CPU.
- Clock @ 166 MHz for AHB bus and AHB peripherals.
- Clock @ 83 MHz for, APB bus and APB peripherals.
- Clock @ 333 MHz for DDR memory interface.

The default values give the maximum allowed clock frequencies. The clock frequencies are fully programmable through dedicated registers.

The reset and clock generator consists of 2 main parts:

- a multiclock generator block
- two internal PLLs

The multiclock generator block receives a reference signal (which is usually delivered by the PLL) and generates all clocks for SPEAr320S IPs according to dedicated programmable registers.

Each PLL uses an oscillator input of 24 MHz to generate a clock signal at a frequency corresponding at the highest of the group. This is the reference signal used by the multiclock generator block to obtain all the other requested clocks for the group. Its main feature is the electromagnetic interference reduction capability.

You can set up the PLL in order to modulate the VCO with a triangular wave. The resulting signal has a spectrum (and power) spread over a small programmable range of frequencies centered on F0 (the VCO frequency), obtaining minimum electromagnetic emissions. This method replaces all the other traditional methods of EMI reduction, such as filtering, ferrite beads, chokes, adding power layers and ground planes to PCBs, metal shielding and so on. This offers important cost savings.

In sleep mode, SPEAr320S runs with the PLL disabled, so the available frequency is 24 MHz or a sub-multiple (/2, /4, /8).

2.26 Vectored interrupt controller (VIC)

SPEAr320S integrates a vectored interrupt controller which provides a software interface to the interrupt system. In any system with an interrupt controller, the software has to determine the source that requests service and where its service routine is loaded. The VIC inside SPEAr320S does both of these in hardware. It supplies the starting address, or vector address, of the service routine corresponding to the highest priority requesting interrupt source.

As in any ARM9-based system, two levels of interrupts are available:

- fast interrupt requests (FIQ), for fast, low latency interrupt handling
- normal interrupt requests (IRQ), for more general interrupts

The interrupt inputs must be level sensitive, active HIGH, and held asserted until the interrupt service routine clears the interrupt. Edge-triggered interrupts are not compatible. The interrupt inputs do not have to be synchronous to HCLK. The VIC does not handle interrupt sources with transient behavior. For example, an interrupt is asserted and then de-

asserted before software can clear the interrupt source. In this case, the CPU acknowledges the interrupt and obtains the vectored address for the interrupt from the VIC, assuming that no other interrupt has occurred to overwrite the vectored address. However, when a transient interrupt occurs, the priority logic of the VIC is not set, and lower priority interrupts can interrupt the transient interrupt service routine, assuming interrupt nesting is permitted.

There are 32 interrupt lines. The VIC uses a bit position for each different interrupt source. The software can control each request line to generate software interrupts. There are 16 vectored interrupts. These interrupts can only generate an IRQ interrupt. The vectored and non-vectored IRQ interrupts provide an address for an interrupt service routine (ISR). The FIQ interrupt has the highest priority, followed by interrupt vector 0 to interrupt vector 15. Non-vectored IRQ interrupts have the lowest priority.

The specific interrupt map for the SPEAr320S device is documented in the companion reference manuals.

2.27 Watchdog timer (WDT)

The ARM watchdog module consists of a 32-bit down counter with a programmable time-out interval that has the capability to generate an interrupt and a reset signal on timing out. The watchdog module is intended to be used to apply a reset to a system in the event of a software failure.

2.28 Real-time clock (RTC)

The real-time clock provides an 1-second resolution clock. This keeps time when the system is inactive and can be used to wake the system up when a programmed alarm time is reached. RTC has a clock trimming feature to compensate for the accuracy of the 32.768 kHz crystal and a secured time update.

Main features:

- Time-of-day clock in 24 hour mode
- Calendar
- Alarm capability
- Isolation mode, allowing RTC to work even if power is not supplied to the rest of the device.

2.29 DMA controller (DMAC)

SPEAr320S provides one DMA controller.

Main features:

- Able to service up to 8 independent DMA channels for serial data transfers between single source and destination (for instance, memory-to-memory, memory-to-peripheral, peripheral to- memory, and peripheral-to-peripheral).
- Each DMA channel can support a unidirectional transfer, with internal four-word FIFO per channel.

2.30 General purpose timers (GPT)

SPEAr320S provides 6 general purpose timers.

Main features:

- Each timer provides a programmable 16-bit counter and a dedicated 4-bit prescaler able to perform a clock division by 1 up to 256 (different input frequencies can be chosen through configuration registers, in the range from 3.96 Hz to 48 MHz)
- Operating modes:
  - Auto-reload mode: when a software-defined value is reached, an interrupt is triggered and the counter automatically restarts from zero
  - Single-shot mode: when a software-defined value is reached, an interrupt is triggered, the counter is stopped and the timer is disabled
- Capture capability (only for 4 timers)

2.31 Pulse width modulators (PWM)

SPEAr320S integrates 4 PWM (pulse width modulation) signal generators.

Main features:

- Prescaler to define the input clock frequency to each timer
- Programmable duty cycle from 0% to 100%
- Programmable pulse length

3 Pin description

This chapter provides a full description of the ball characteristics and the signal multiplexing of SPEAr320S device.

Section 3.1 shows the pin/ball map of SPEAr320S.

Section 3.2 lists the required external components to connect.

Section 3.3 describes some dedicated pins, such as:

- *Clock, reset and 3V3 comparator pins*
- *Power supply pins*
- *Debug pins*
- *Non-multiplexed pins*

Section 3.4 provides a complete description of the shared IO pins (PL_GPIOs) and their configuration modes, as well as detailed information on all multiplexed signals, grouped by IP.

Section 3.5 explains the available debug modes.

The following table defines the table headers and abbreviations used in this chapter.

Table 5. Headers/abbreviations

Header	Description	Abbreviations
Group	Grouping of signals of the same type/functional block.	–
Signal name	Name of signal multiplexed on each ball.	–
Direction (Dir.)	Indicates the direction of the signal.	I= Input O= Output IO= Input/output
PL_GPIO_# /Ball	PL_GPIO and ball number associated with each signal on the package.	–
Configuration mode	Indicates the available configuration mode among the following ones: – Mode 1 – Mode 2 – Mode 3 – Mode 4 – Alternate function – Extended mode See *Section 3.4.2* for the description of each mode.	–
Pin type	Pad type information	PU= Pull Up PD= Pull Down GND= Ground
Value	Indicates the electrical value on the ball.	–

3.1 Pin/ball map

Figure 2. SPEAr320S pin/ball map

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17
A	PL_GPIO_13	PL_GPIO_14	PL_GPIO_19	PL_GPIO_23	PL_GPIO_26	PL_GPIO_28	PL_GPIO_29	PL_GPIO_38	PL_GPIO_39	PL_GPIO_44	PL_GPIO_46	PL_GPIO_50	PL_GPIO_55	PL_GPIO_60	PL_GPIO_62	PL_GPIO_69	PL_GPIO_73
B	PL_GPIO_6	PL_GPIO_9	PL_GPIO_15	PL_GPIO_20	PL_GPIO_24	PL_GPIO_27	PL_GPIO_30	PL_GPIO_37	PL_GPIO_40	PL_GPIO_45	PL_GPIO_48	PL_GPIO_52	PL_GPIO_59	PL_GPIO_65	PL_GPIO_68	PL_GPIO_72	PL_GPIO_77
C	PL_GPIO_4	PL_GPIO_8	PL_GPIO_10	PL_GPIO_17	PL_GPIO_21	PL_GPIO_25	PL_GPIO_31	PL_GPIO_36	PL_GPIO_41	PL_GPIO_47	PL_GPIO_49	PL_GPIO_56	PL_GPIO_63	PL_GPIO_67	PL_GPIO_70	PL_GPIO_74	PL_GPIO_81
D	PL_GPIO_3	PL_GPIO_5	PL_GPIO_7	PL_GPIO_12	PL_GPIO_18	PL_GPIO_22	PL_GPIO_32	PL_GPIO_35	PL_GPIO_42	PL_GPIO_51	PL_GPIO_53	PL_GPIO_58	PL_GPIO_64	PL_GPIO_71	PL_GPIO_78	PL_GPIO_80	PL_GPIO_84
E	RTC_XO	RTC_XI	PL_GPIO_1	PL_GPIO_2	PL_GPIO_11	PL_GPIO_16	PL_GPIO_33	PL_GPIO_34	PL_GPIO_43	PL_GPIO_54	PL_GPIO_57	PL_GPIO_61	PL_GPIO_66	PL_GPIO_75	PL_GPIO_82	PL_GPIO_83	PL_GPIO_86
F	RTC_vdd1v5	RTC_gnd	PL_GPIO_0	DIGITAL_ GNDBG COMP	digital_vdde 3v3	digital_vdde 3v3	digital_vdde 3v3	vdd	vdd	digital_vdde 3v3	digital_vdde 3v3	digital_vdde 3v3	PL_GPIO_76	PL_GPIO_79	PL_GPIO_85	PL_GPIO_88	PL_GPIO_89
G	DITH_pll_vss_ ana	DITH_pll_vdd_ ana	USB_DEVICE_ VBUS	DIGITAL_ REXT	digital_vdde 3v3	gnd	gnd	gnd	gnd	gnd	gnd	vdd	PL_GPIO_87	PL_GPIO_90	PL_GPIO_91	PL_GPIO_92	PL_GPIO_93
H	USB_HOST1_ DP	USB_HOST1_ DM	USB_HOST1_ VBUS	USB_HOST0_ OVERCUR	vdd	gnd	gnd	gnd	gnd	gnd	gnd	vdd	PL_GPIO_94	PL_GPIO_95	PL_GPIO_96	PL_GPIO_97	PL_CLK4
J	USB_HOST1_ vdd3v3	gnd	USB_HOST0_ VBUS	USB_HOST1_ OVERCUR	vdd	gnd	gnd	gnd	gnd	gnd	gnd	digital_vdde 3v3	DDR2_EN	BOOT_SEL	TEST_4	PL_CLK3	PL_CLK2
K	USB_HOST0_ DP	USB_HOST0_ DM	USB_HOST1_ vdd2v5	USB_HOST0_ vdd3v3	USB_TXR TUNE	gnd	gnd	gnd	gnd	gnd	gnd	digital_vdde 3v3	TEST_3	TEST_2	TEST_1	TEST_0	PL_CLK1
L	gnd	USB_HOST0_ vdd2v5	gnd	USB_ANALOG TEST	gnd	gnd	gnd	gnd	gnd	gnd	vdd	digital_vdde 3v3	TMS	TDI	TDO	nTRST	TCK
M	USB_DEVICE_ DP	USB_DEVICE_ DM	USB_HOST1_ HOST0_ DEVICE_ Dvdd1v2	dith_vdd2v5	DDR_vdde1v8	vdd	vdd	gnd	gnd	gnd	vdd	digital_vdde 3v3	SMI_DATAIN	SMI_DATAOUT	SMI_CS_0	SMI_CS_1	MRESET
N	USB_DEVICE _vdd2v5	gnd	USB_DEVICE _vdd3v3	dith_vss2v5	DDR_vdde1v8	DDR_vdde1v8	DDR_vdde1v8	DDR_vdde1v8	DDR_vdde1v8	DDR_vdde1v8	DDR_vdde1v8	ADC_agnd	ADC_avdd	ADC_VREFN	AIN_1	AIN_0	SMI_CLK
P	MCLK_XI	MCLK_XO	MCLK_GND	DDR_MEM_ COMP2V5_ REXT	DDR_MEM_ ADDR_9	DDR_MEM_ ADDR_10	DDR_MEM_ BA_0	DDR_MEM_ BA_1	DDR_MEM_ CS_0	DDR_MEM_ VREF	DDR_MEM_ DQ_0	DDR_MEM_ DQ_6	DDR_MEM_ DQ_7	ADC_VREFP	AIN_4	AIN_3	AIN_2
R	MCLK_VDD	MCLK_ VDD2V5	MCLK_ GNDSUB	DDR_MEM_ COMP2V5_ GNDBGCOMP	DDR_MEM_ ADDR_8	DDR_MEM_ ADDR_11	DDR_MEM_ ADDR_14	DDR_MEM_ BA_2	DDR_MEM_ CS_1	DDR_MEM_ GATE_OPEN _0	DDR_MEM_ DQ_1	DDR_MEM_ DQ_5	DDR_MEM_ DQ_15	DDR_MEM_ GATE_OPEN _1	AIN_7	AIN_6	AIN_5
T	DDR_MEM_ ADDR_1	DDR_MEM_ ADDR_0	DDR_MEM_ ODT_0	DDR_MEM_ ODT_1	DDR_MEM_ ADDR_7	DDR_MEM_ ADDR_12	DDR_MEM_ WE	DDR_MEM_ CAS	DDR_MEM_ CLKP	nDDR_MEM_ DQS_0	DDR_MEM_ DQ_2	DDR_MEM_ DQ_4	DDR_MEM_ DQ_14	DDR_MEM_ DM_1	nDDR_MEM_ DQS_1	DDR_MEM_ DQ_9	DDR_MEM_ DQ_8
U	DDR_MEM_ ADDR_2	DDR_MEM_ ADDR_3	DDR_MEM_ ADDR_4	DDR_MEM_ ADDR_5	DDR_MEM_ ADDR_6	DDR_MEM_ ADDR_13	DDR_MEM_ CLKEN	DDR_MEM_ RAS	DDR_MEM_ CLKN	DDR_MEM_ DQS_0	DDR_MEM_ DQ_3	DDR_MEM_ DM_0	DDR_MEM_ DQ_13	DDR_MEM_ DQ_12	DDR_MEM_ DQS_1	DDR_MEM_ DQ_11	DDR_MEM_ DQ_10

3.2 Required external components

Some pads require the use of an external component. Please follow the instructions below to ensure the proper functioning of the device:

1. DDR_COMP_1V8: place an external 121 kΩ resistor between ball P4 and ball R4
2. USB_TX_RTUNE: connect an external 43.2 Ω pull-down resistor to ball K5
3. DIGITAL_REXT: place an external 121 kΩ resistor between ball G4 and ball F4
4. DITH_VDD_2V5: add a ferrite bead to ball M4

3.3 Dedicated pins description

3.3.1 Clock, reset and 3V3 comparator pins

Table 6. MCLK, RTC, Reset and 3.3 V comparator pins description

Group	Signal name	Description	Dir.	Pin type	Ball
Master clock (MCLK)	MCLK_XI	24 MHz (typical) crystal in	I	Oscillator 2.5 V capable	P1
	MCLK_XO	24 MHz (typical) crystal out	O		P2
Real-time clock (RTC)	RTC_XI	32 kHz crystal in	I	Oscillator 1V5 capable	E2
	RTC_XO	32 kHz crystal out	O		E1
Reset	MRESET	Main reset	I	TTL Schmitt trigger input buffer, 3.3 V tolerant	M17
3.3 V comparator	DIGITAL_REXT	Configuration	O	Analog, 3.3 V capable	G4
	DIGITAL_GNDBGCOMP	Power	Power	Power	F4

3.3.2 Power supply pins

Table 7. Power supply pins description

Group	Signal name	Value	Ball
Digital ground	GND	0 V	G6 G7 G8 G9 G10 G11 H6 H7 H8 H9 H10 H11 J6 J7 J8 J9 J10 J11 K6 K7 K8 K9 K10 K11 L6 L7 L8 L9 L10 M8 M9 M10
	USB_HOST1_HOST0_DEVICE_DVSS		L5
Analog ground	RTC_GND	0 V	F2
	DITH_PLL_VSS_ANA		G1
	USB_HOST1_VSSA		J2
	USB_HOST0_VSSA		L1
	USB_COMMON_VSSAC		L3
	USB_DEVICE_VSSA		N2
	DITH_VSS2V5		N4
	MCLK_GND		P3
	MCLK_GNDSUB		R3
	ADC_AGND		N12
IO	DIGITAL_VDDE3V3	3.3 V	F5 F6 F7 F10 F11 F12 G5 J12 K12 L12 M12
Core	VDD	1.2 V	F8 F9 G12 H5 H12 J5 L11 M6 M7 M11
USB Host0 PHY	USB_HOST0_VDD2V5	2.5 V	L2
	USB_HOST0_VDD3V3	3.3 V	K4
USB Host1 PHY	USB_HOST1_VDD2V5	2.5 V	K3
	USB_HOST1_VDD3V3	3.3 V	J1
USB Device PHY	USB_DEVICE_VDD2V5	2.5 V	N1
	USB_DEVICE_VDD3V3	3.3 V	N3
	USB_HOST1_HOST0_DEVICE_DVDD1V2	1.2 V	M3
OSCI (MCLK)	MCLK_VDD	1.2 V	R1
	MCLK_VDD2V5	2.5 V	R2
PLL1	DITH_PLL_VDD_ANA	2.5 V	G2
PLL2	DITH_VDD_2V5	2.5 V	M4
DDR IO	DDR_VDDE1V8	1.8 V	M5 N5 N6 N7 N8 N9 N10 N11
ADC	ADC_AVDD	2.5 V	N13
OSCI (RTC)	RTC_VDD1V5	1.5 V	F1

Note: All the VDD 2V5 power supplies are analog VDD.

3.3.3 Debug pins

Table 8. Debug pins description

Signal name	Description	Dir.	Pin type	Ball
TEST_0	Test configuration ports. For functional mode, they have to be set to zero.	I	TTL input buffer, 3.3 V tolerant, PD	K16
TEST_1				K15
TEST_2				K14
TEST_3				K13
TEST_4				J15
BOOT_SEL	Reserved, to be fixed at high level			J14
nTRST	Test reset input	I	TTL Schmitt trigger input buffer, 3.3 V tolerant, PU	L16
TDO	Test data output	O	TTL output buffer, 3.3 V capable 4 mA	L15
TCK	Test clock	I	TTL Schmitt trigger input buffer, 3.3 V tolerant, PU	L17
TDI	Test data input	I		L14
TMS	Test mode select	I		L13

Note: See also Section 3.5: PL_GPIO pin sharing for debug modes.

3.3.4 Non-multiplexed pins

Table 9. SMI pins description

Signal name	Description	Dir.	Pin type	Ball
SMI_DATAIN	Serial Flash input data	I	TTL Input Buffer 3.3 V tolerant, PU	M13
SMI_DATAOUT	Serial Flash output data	O	TTL output buffer 3.3 V capable 4 mA	M14
SMI_CLK	Serial Flash clock	IO		N17
SMI_CS_0	Serial Flash chip select	O		M15
SMI_CS_1				M16

Table 10. USB pins description

Group	Signal name	Description	Dir.	Pin type	Ball
USB Device	USB_DEVICE_DP	USB Device D+	IO	Bidirectional analog buffer 5 V tolerant	M1
	USB_DEVICE_DM	USB Device D-			M2
	USB_DEVICE_VBUS	USB Device VBUS	I	TTL input buffer 3.3 V tolerant, PD	G3
USB Host	USB_HOST1_DP	USB Host1 D+	IO	Bidirectional analog buffer 5 V tolerant	H1
	USB_HOST1_DM	USB Host1 D-			H2
	USB_HOST1_VBUS	USB Host1 VBUS	O	TTL output buffer 3.3 V capable, 4 mA	H3
	USB_HOST1_OVERCUR	USB Host1 Over-Current	I	TTL input buffer 3.3 V tolerant, PD	J4
	USB_HOST0_DP	USB Host0 D+	IO	Bidirectional analog buffer 5 V tolerant	K1
	USB_HOST0_DM	USB Host0 D-			K2
	USB_HOST0_VBUS	USB Host0 VBUS	O	TTL output buffer 3.3 V capable, 4 mA	J3
	USB_HOST0_OVERCUR	USB Host0 Over-current	I	TTL Input Buffer 3.3 V tolerant, PD	H4
USB	USB_TXRTUNE	Reference resistor	O	Analog	K5
	USB_ANALOG_TEST	Analog test output	O	Analog	L4

Table 11. ADC pins description

Signal name	Description	Dir.	Pin type	Ball
AIN_0	ADC analog input channel	I	Analog buffer 2.5 V tolerant	N16
AIN_1				N15
AIN_2				P17
AIN_3				P16
AIN_4				P15
AIN_5				R17
AIN_6				R16
AIN_7				R15
ADC_VREFN	ADC negative voltage reference			N14
ADC_VREFP	ADC positive voltage reference			P14

Table 12. DDR pins description

Signal name	Description	Dir.	Pin type	Ball
DDR_MEM_ADD_0	Address Line	O	SSTL_2/SSTL_18	T2
DDR_MEM_ADD_1				T1
DDR_MEM_ADD_2				U1
DDR_MEM_ADD_3				U2
DDR_MEM_ADD_4				U3
DDR_MEM_ADD_5				U4
DDR_MEM_ADD_6				U5
DDR_MEM_ADD_7				T5
DDR_MEM_ADD_8				R5
DDR_MEM_ADD_9				P5
DDR_MEM_ADD_10				P6
DDR_MEM_ADD_11				R6
DDR_MEM_ADD_12				T6
DDR_MEM_ADD_13				U6
DDR_MEM_ADD_14				R7
DDR_MEM_BA_0	Bank select	O		P7
DDR_MEM_BA_1				P8
DDR_MEM_BA_2				R8
DDR_MEM_RAS	Row address strobe	O		U8
DDR_MEM_CAS	Column address strobe	O		T8
DDR_MEM_WE	Write enable	O		T7
DDR_MEM_CLKEN	Clock enable	O		U7
DDR_MEM_CLKP	Differential clock	O	Differential SSTL_2/ SSTL_18	T9
DDR_MEM_CLKN				U9
DDR_MEM_CS_0	Chip select	O	SSTL_2/ SSTL_18	P9
DDR_MEM_CS_1				R9
DDR_MEM_ODT_0	On-die termination enable lines	IO		T3
DDR_MEM_ODT_1				T4

Table 12. DDR pins description (continued)

Signal name	Description	Dir.	Pin type	Ball
DDR_MEM_DQ_0	Data lines (lower byte)	IO	SSTL_2/ SSTL_18	P11
DDR_MEM_DQ_1				R11
DDR_MEM_DQ_2				T11
DDR_MEM_DQ_3				U11
DDR_MEM_DQ_4				T12
DDR_MEM_DQ_5				R12
DDR_MEM_DQ_6				P12
DDR_MEM_DQ_7				P13
DDR_MEM_DQS_0	Lower data strobe	O	Differential SSTL_2/ SSTL_18	U10
nDDR_MEM_DQS_0				T10
DDR_MEM_DM_0	Lower data mask	O	SSTL_2/ SSTL_18	U12
DDR_MEM_GATE_OPEN_0	Lower gate open	IO		R10
DDR_MEM_DQ_8	Data lines (upper byte)	IO		T17
DDR_MEM_DQ_9				T16
DDR_MEM_DQ_10				U17
DDR_MEM_DQ_11				U16
DDR_MEM_DQ_12				U14
DDR_MEM_DQ_13				U13
DDR_MEM_DQ_14				T13
DDR_MEM_DQ_15				R13
DDR_MEM_DQS_1	Upper data strobe	IO	Differential SSTL_2/ SSTL_18	U15
nDDR_MEM_DQS_1				T15
DDR_MEM_DM_1	Upper data mask	IO	SSTL_2/ SSTL_18	T14
DDR_MEM_GATE_OPEN_1	Upper gate open			R14
DDR_MEM_VREF	Reference voltage	I	Analog	P10
DDR_MEM_COMP2V5_GNDBGCOMP	Return for external resistors	Power	Power	R4
DDR_MEM_COMP2V5_REXT	External resistor	Power	Analog	P4
DDR2_EN	Configuration	I	TTL Input Buffer 3.3 V Tolerant, PU	J13

3.4 Shared IO pins (PL_GPIOs)

The 98 PL_GPIO and 4 PL_CLK pins have the following characteristics:

- Output buffer: TTL 3.3 V capable up to 10 mA
- Input buffer: TTL, 3.3 V tolerant, selectable internal pull up/pull down (PU/PD)

The PL_GPIOs can be configured in different modes. This allows SPEAr320S to be tailored for use in various applications like:

- Metering concentrators
- Large power supply controllers
- Small printers

3.4.1 PL_GPIO pins description

Table 13. PL_GPIO pins description

Group	Signal name	Ball	Dir.	Description	Pin type
PL_GPIOs	PL_GPIO_97... PL_GPIO_0	(See the *Table 15*)	IO	General purpose IO or multiplexed pins (see *Table 15*)	(See the introduction of *Section 3.4* here above)
	PL_CLK1... PL_CLK4			Programmable logic external clocks	

3.4.2 Configuration modes

This section describes the main operating modes created by using a selection of the embedded IPs.

The following modes can be selected by software through programming of dedicated configuration registers (see *Figure 3: Hierarchical multiplexing scheme*).

- *Mode 1: HMI automation mode*
- *Mode 2: MII automation networking mode*
- *Mode 3: Expanded automation mode*
- *Mode 4: Printer mode*
- *Extended mode: RMII automation networking mode*

Note: SPEAr320S is backward compatible with SPEAr320 as for modes 1 to 4. When the "extended mode enable" register is set, the signals can be selected from all the available modes (pin by pin). See also Section 3.4.6: Multiplexing scheme.

Table 13 shows the IO functions available in each mode.

Mode 1 is the default mode for SPEAr320S.

Mode 1: HMI automation mode

The HMI automation operating mode mainly provides:

- LCD interface (up to 1024x768, 24-bit LCD controller, TFT and STN panels)
- NAND Flash interface (8 bits, 4 chip selects)
- 2 CAN 2.0 interfaces
- 3 UARTs
  - 1 with hardware flow control (up to 3 Mbps)
  - 2 with software flow control (baud rate up to 7 Mbps)
- Touchscreen facilities
- 3 independent SSP synchronous serial ports (SPI, Microwire or TI protocol)
- 2 independent I2C interfaces
- GPIOs with interrupt capability
- SDIO interface supporting SPI, SD1, SD4 and SD8 mode

Mode 2: MII automation networking mode

The MII automation networking operating mode mainly provides:

- NAND Flash interface (8 bits, 4 chip selects)
- 2 CAN 2.0 interfaces
- 2 MII interfaces
- 7 UARTs
  - 1 with hardware flow control (up to 3 Mbps)
  - 6 with software flow control (baud rate up to 7 Mbps)
- 3 independent SSP synchronous serial ports (SPI, Microwire or TI protocol)
- 2 independent I2C interfaces
- GPIOs with interrupt capability
- SDIO interface supporting SPI, SD1, SD4 and SD8 mode

Mode 3: Expanded automation mode

The Expanded automation operating mode mainly provides:

- External memory interface (16 data bits, 24 address bits and 4 chip selects)
- NAND Flash interface (8-16 bits and 4 chip selects shared with EMI)
- 2 CAN 2.0 interfaces
- MII interface
- 6 UARTs
  - 1 with hardware flow control (up to 3 Mbps)
  - 1 with hardware flow control (baud rate up to 7 Mbps)
  - 4 with software flow control (baud rate up to 7 Mbps)
- SSP port
- 2 independent I2C interfaces
- Up to 4 PWM outputs
- GPIOs with interrupt capabilities

Mode 4: Printer mode

The printer operating mode mainly provides:

- NAND Flash interface (8 bits, 4 chip selects)
- Up to 4 PWM outputs
- 7 UARTs
  - 1 with hardware flow control (up to 3 Mbps)
  - 1 with hardware flow control (baud rate up to 7 Mbps)
  - 5 with software flow control (baud rate up to 7 Mbps)
- SDIO interface supporting SPI, SD1, SD4 and SD8 mode
- Standard parallel port (SPP device implementation)
- 2 independent SSP synchronous serial ports (SPI, Microwire or TI protocol)
- 2 independent I2C interfaces
- GPIOs with interrupt capabilities

Extended mode: RMII automation networking mode

The RMII automation mode provides the flexibility of using most of the functionality offered by the other configuration modes (see *Table 15: PL_GPIO multiplexing scheme*). When this mode is enabled and the registers are used in their default state, the following features are available:

- 2 independent SSP synchronous serial ports (SPI, Microwire or TI protocol)
- 2 RMII interfaces
- 2 independent I2C interfaces
- Standard parallel port (SPP device implementation)
- 7 UARTs
  - 1 with hardware flow control (up to 3 Mbps)
  - 1 with hardware flow control (baud rate up to 7 Mbps)
  - 5 with software flow control (baud rate up to 7 Mbps)

3.4.3 Alternate functions

Other peripheral functions are listed in the Alternate Functions column of *Table 13: PL_GPIO pins description* and can be individually enabled/disabled configuring the bits of a dedicated control register.

3.4.4 Boot pins

The status of the boot pins is read at startup by the BootROM.

Table 14. Boot pins description

B3-B0	Boot device
0000	USB Device
0011	Serial NOR Flash (SMI interface)
0100	Parallel 8-bit NOR Flash (EMI interface)
0101	Parallel 16-bit NOR Flash (EMI interface)
0110	Parallel 8-bit NAND Flash (FSMC interface)
0111	Parallel 16-bit NAND Flash (FSMC interface)
1010	UART 0
Other	Reserved

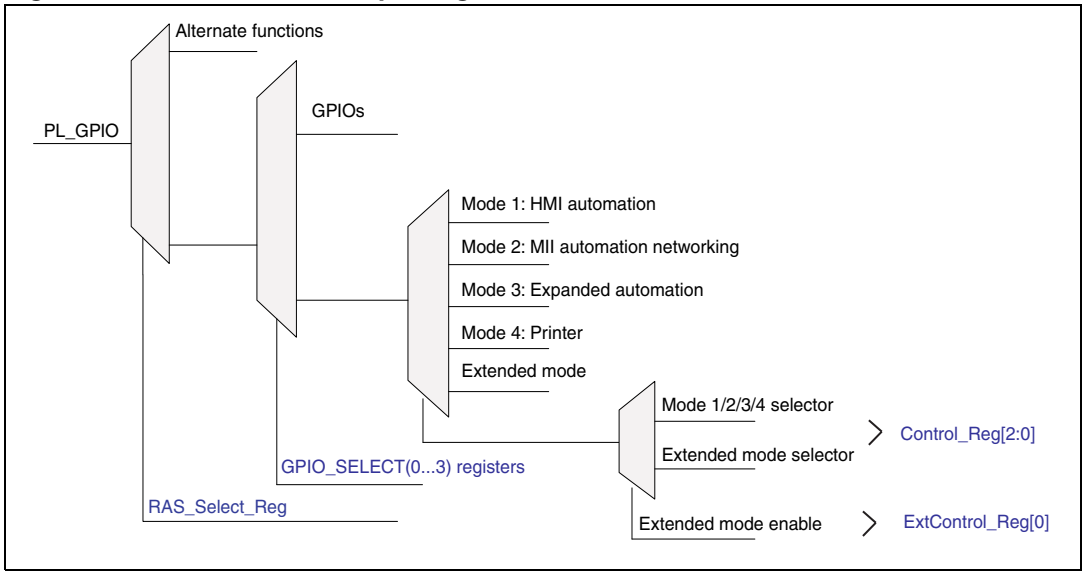
3.4.5 GPIOs

The PL_GPIO pins can be used as software-controlled general purpose I/Os if they are not used by the interfaces of embedded IPs mapped on same pins.

3.4.6 Multiplexing scheme

To provide the best I/O multiplexing flexibility and the higher number of GPIOs for ARM controlled input-output function, the following hierarchical multiplexing scheme has been implemented.

Figure 3. Hierarchical multiplexing scheme



Note: Extended mode selector [2:0] registers are dedicated to each pin.

Table 15. PL_GPIO multiplexing scheme

PL_GPIO_# / ball number	Configuration mode (SW defined)					Alternate function (SW defined)	Boot pins	Function in GPIO alternative mode
	1	2	3	4	Extended			
PL_GPIO_97/H16	CLD0	MII1_TXCLK	EMI_A0	I2C2_SDA	SSP1_MOSI			GPIO_97
PL_GPIO_96/H15	CLD1	MII1_TXD0	EMI_A1	I2C2_SCL	SSP1_CLK			GPIO_96
PL_GPIO_95/H14	CLD2	MII1_TXD1	EMI_A2	UART3_TX	SSP1_SS0			GPIO_95
PL_GPIO_94/H13	CLD3	MII1_TXD2	EMI_A3	UART3_RX	SSP1_MISO			GPIO_94
PL_GPIO_93/G17	CLD4	MII1_TXD3	EMI_A4	UART4_TX	SSP2_MOSI			GPIO_93
PL_GPIO_92/G16	CLD5	MII1_TXEN	EMI_A5	UART4_RX	SSP2_CLK			GPIO_92
PL_GPIO_91/G15	CLD6	MII1_TXER	EMI_A6	UART5_TX	SSP2_SS0			GPIO_91
PL_GPIO_90/G14	CLD7	MII1_RXCLK	EMI_A7	UART5_RX	SSP2_MISO			GPIO_90
PL_GPIO_89/F17	CLD8	MII1_RXDV	EMI_A8	UART6_TX	PWM0			GPIO_89
PL_GPIO_88/F16	CLD9	MII1_RXER	EMI_A9	UART6_RX	PWM1			GPIO_88
PL_GPIO_87/G13	CLD10	MII1_RXD0	EMI_A10	0	PWM2			GPIO_87
PL_GPIO_86/E17	CLD11	MII1_RXD1	EMI_A11	0	PWM3			GPIO_86
PL_GPIO_85/F15	CLD12	MII1_RXD2	EMI_A12	SPP_DATA0	UART1_CTS			GPIO_85
PL_GPIO_84/D17	CLD13	MII1_RXD3	EMI_A13	SPP_DATA1	UART1_DTR			GPIO_84
PL_GPIO_83/E16	CLD14	MII1_COL	EMI_A14	SPP_DATA2	UART1_RI			GPIO_83
PL_GPIO_82/E15	CLD15	MII1_CRS	EMI_A15	SPP_DATA3	UART1_DCD			GPIO_82
PL_GPIO_81/C17	CLD16	MII1_MDIO	EMI_A16	SPP_DATA4	UART1_DSR			GPIO_81
PL_GPIO_80/D16	CLD17	MII1_MDC	EMI_A17	SPP_DATA5	UART1_RTS			GPIO_80
PL_GPIO_79/F14	CLD18	0	EMI_A18	SPP_DATA6	UART_RS485_TX			GPIO_79
PL_GPIO_78/D15	CLD19	0	EMI_A19	SPP_DATA7	UART_RS485_RX			GPIO_78
PL_GPIO_77/B17	CLD20	0	EMI_A20	SPP_STRBn	UART_RS485_OE			GPIO_77
PL_GPIO_76/F13	CLD21	0	EMI_A21	SPP_ACKn	I2C2_SDA			GPIO_76
PL_GPIO_75/E14	CLD22	0	EMI_A22	SPP_BUSY	I2C2_SCL			GPIO_75
PL_GPIO_74/C16	CLD23	0	EMI_A23	SPP_PERROR	UART3_TX			GPIO_74

Table 15. PL_GPIO multiplexing scheme (continued)

PL_GPIO_# / ball number	Configuration mode (SW defined)					Alternate function (SW defined)	Boot pins	Function in GPIO alternative mode
	1	2	3	4	Extended			
PL_GPIO_73/A17	CLAC	0	EMI_D8/ FSMC_D8	SPP_SELECT	UART3_RX			GPIO_73
PL_GPIO_72/B16	CLFP	0	EMI_D9/ FSMC_D9	SPP_AUTOFDn	UART4_TX			GPIO_72
PL_GPIO_71/D14	CLLP	0	EMI_D10/ FSMC_D10	SPP_FAULTn	UART4_RX			GPIO_71
PL_GPIO_70/C15	CLLE	0	EMI_D11/ FSMC_D11	SPP_INITn	UART5_TX			GPIO_70
PL_GPIO_69/A16	CLPOWER	0	EMI_WAIT	SPP_SELINn	UART5_RX			GPIO_69
PL_GPIO_68/B15	FSMC_D0	FSMC_D0	EMI_D0/ FSMC_D0	FSMC_D0	SSP1_MOSI			GPIO_68
PL_GPIO_67/C14	FSMC_D1	FSMC_D1	EMI_D1/ FSMC_D1	FSMC_D1	SSP1_CLK			GPIO_67
PL_GPIO_66/E13	FSMC_D2	FSMC_D2	EMI_D2/ FSMC_D2	FSMC_D2	SSP1_SS0			GPIO_66
PL_GPIO_65/B14	FSMC_D3	FSMC_D3	EMI_D3/ FSMC_D3	FSMC_D3	SSP1_MISO			GPIO_65
PL_GPIO_64/D13	FSMC_D4	FSMC_D4	EMI_D4/ FSMC_D4	FSMC_D4	SSP2_MOSI			GPIO_64
PL_GPIO_63/C13	FSMC_D5	FSMC_D5	EMI_D5/ FSMC_D5	FSMC_D5	SSP2_CLK			GPIO_63
PL_GPIO_62/A15	FSMC_D6	FSMC_D6	EMI_D6/ FSMC_D6	FSMC_D6	SSP2_SS0		H7	GPIO_62
PL_GPIO_61/E12	FSMC_D7	FSMC_D7	EMI_D7/ FSMC_D7	FSMC_D7	SSP2_MISO		H6	GPIO_61
PL_GPIO_60/A14	FSMC_ADDR_LE	FSMC_ADDR_LE	FSMC_ADDR_LE	FSMC_ADDR_LE	PWM0		H5	GPIO_60
PL_GPIO_59/B13	FSMC_WE	FSMC_WE	EMI_WE/ FSMC_WE	FSMC_WE	PWM1		H4	GPIO_59
PL_GPIO_58/D12	FSMC_RE	FSMC_RE	EMI_OE/ FSMC_RE	FSMC_RE	PWM2		H3	GPIO_58
PL_GPIO_57/E11	FSMC_CMD_ LE	FSMC_CMD_ LE	FSMC_CMD_LE	FSMC_CMD_LE	PWM3		H2	GPIO_57
PL_GPIO_56/C12	FSMC_RDY /BSY	FSMC_RDY/ BSY	FSMC_RDY/BSY	FSMC_RDY/ BSY			H1	GPIO_56
PL_GPIO_55/A13	FSMC_CS0	FSMC_CS0	EMI_CE0/ FSMC_CS0	FSMC_CS0			H0	GPIO_55
PL_GPIO_54/E10	FSMC_CS1	FSMC_CS1	EMI_CE1/ FSMC_CS1	FSMC_CS1			B3	GPIO_54
PL_GPIO_53/D11	FSMC_CS2	FSMC_CS2	EMI_CE2/ FSMC_CS2	FSMC_CS2	UART3_TX		B2	GPIO_53
PL_GPIO_52/B12	FSMC_CS3	FSMC_CS3	EMI_CE_3/ FSMC_CS3	FSMC_CS3	UART3_RX		B1	GPIO_52
PL_GPIO_51/D10	SD_CD	SD_CD	EMI_BYTEN0	SD_CD	SSP1_MOSI		B0	GPIO_51
PL_GPIO_50/A12	SD_DAT7	SD_DAT7	EMI_BYTEN1	SD_DAT7	SSP1_CLK	TMR_CPTR4		GPIO_50
PL_GPIO_49/C11	SD_DAT6	SD_DAT6	EMI_D12/ FSMC_D12	SD_DAT6	SSP1_SS0	TMR_CPTR3		GPIO_49
PL_GPIO_48/B11	SD_DAT5	SD_DAT5	EMI_D13/ FSMC_D13	SD_DAT5	SSP1_MISO	TMR_CPTR2		GPIO_48

Table 15. PL_GPIO multiplexing scheme (continued)

PL_GPIO_# / ball number	Configuration mode (SW defined)					Alternate function (SW defined)	Boot pins	Function in GPIO alternative mode
	1	2	3	4	Extended			
PL_GPIO_47/C10	SD_DAT4	SD_DAT4	EMI_D14/ FSMC_D14	SD_DAT4	SSP2_MOSI	TMR_CPTR1		GPIO_47
PL_GPIO_46/A11	SD_DAT3	SD_DAT3	EMI_D15/ FSMC_D15	SD_DAT3	SSP2_CLK	TMR_CLK4		GPIO_46
PL_GPIO_45/B10	SD_DAT2	SD_DAT2	UART1_DCD	SD_DAT2	SSP2_SS0	TMR_CLK3		GPIO_45
PL_GPIO_44/A10	SD_DAT1	SD_DAT1	UART1_DSR	SD_DAT1	SSP2_MISO	TMR_CLK2		GPIO_44
PL_GPIO_43/E9	SD_DAT0	SD_DAT0	UART1_RTS	SD_DAT0	PWM0	TMR_CLK1		GPIO_43
PL_GPIO_42/D9	I2S_RX	I2S_RX	UART3_TX	0	PWM1	UART0_DTR		GPIO_42
PL_GPIO_41/C9	I2S_TX	I2S_TX	UART3_RX	0	PWM2	UART0_RI		GPIO_41
PL_GPIO_40/B9	I2S_LR	I2S_LR	UART4_TX	0	PWM3	UART0_DSR		GPIO_40
PL_GPIO_39/A9	I2S_CLK	I2S_CLK	UART4_RX	0	SSP1_MOSI	UART0_DCD		GPIO_39
PL_GPIO_38/A8	PWM0	PWM0	UART5_TX	0	SSP1_CLK	UART0_CTS		GPIO_38
PL_GPIO_37/B8	PWM1	PWM1	UART5_RX	0	SSP1_SS0	UART0_RTS		GPIO_37
PL_GPIO_36/C8	TOUCHSCREEN X	0	UART1_CTS	UART1_CTS	SSP1_MISO	SSP0_CS4		GPIO_36
PL_GPIO_35/D8	audio_over_samp_clk	audio_over_samp_clk	UART1_DTR	UART1_DTR	SSP2_MOSI	SSP0_CS3		GPIO_35
PL_GPIO_34/E8	SD_LED / PWM2	SD_LED / PWM2	UART1_RI	UART1_RI	SSP2_CLK	SSP0_CS2		GPIO_34
PL_GPIO_33/E7	CAN0_TX	CAN0_TX	CAN0_TX	UART1_DCD	SSP2_SS0	basGPIO5		GPIO_33
PL_GPIO_32/D7	CAN0_RX	CAN0_RX	CAN0_RX	UART1_DSR	SSP2_MISO	basGPIO4		GPIO_32
PL_GPIO_31/C7	CAN1_TX	CAN1_TX	CAN1_TX	UART1_RTS	PWM0	basGPIO3		GPIO_31
PL_GPIO_30/B7	CAN1_RX	CAN1_RX	CAN1_RX	0	PWM1	basGPIO2		GPIO_30
PL_GPIO_29/A7	UART1_TX	UART1_TX	UART1_TX	UART1_TX	PWM2	basGPIO1		GPIO_29
PL_GPIO_28/A6	UART1_RX	UART1_RX	UART1_RX	UART1_RX	PWM3	basGPIO0		GPIO_28
PL_GPIO_27/B6	Reserved	0	Reserved	Reserved	RMII0_TXD0	MII0_TXCLK		GPIO_27
PL_GPIO_26/A5	Reserved	0	Reserved	Reserved	RMII0_RXD0	MII0_TXD0		GPIO_26
PL_GPIO_25/C6	Reserved	0	0	Reserved	RMII1_TXD0	MII0_TXD1		GPIO_25
PL_GPIO_24/B5	Reserved	0	0	Reserved	RMII1_RXD0	MII0_TXD2		GPIO_24
PL_GPIO_23/A4	Reserved	0	Reserved	Reserved	RMII1_TX_EN	MII0_TXD3		GPIO_23

Table 15. PL_GPIO multiplexing scheme (continued)

PL_GPIO_# / ball number	Configuration mode (SW defined)					Alternate function (SW defined)	Boot pins	Function in GPIO alternative mode
	1	2	3	4	Extended			
PL_GPIO_22/D6	Reserved	0	Reserved	Reserved	RMII_REF_CLK	MII0_TXEN		GPIO_22
PL_GPIO_21/C5	Reserved	0	Reserved	Reserved	RMII1_TXD1	MII0_TXER		GPIO_21
PL_GPIO_20/B4	SSP1_MOSI	I2C2_SDA	0	SSP1_MOSI	RMII1_RXD1	MII0_RXCLK		GPIO_20
PL_GPIO_19/A3	SSP1_CLK	I2C2_SCL	0	SSP1_CLK	RMII1_CRS_DV	MII0_RXDV		GPIO_19
PL_GPIO_18/D5	SSP1_SS0	0	0	SSP1_SS0	RMII1_RX_ER	MII0_RXER		GPIO_18
PL_GPIO_17/C4	SSP1_MISO	0	0	SSP1_MISO	RMII0_TXD1	MII0_RXD0		GPIO_17
PL_GPIO_16/E6	SSP2_MOSI	UART3_TX	0	0	RMII0_TX_EN	MII0_RXD1		GPIO_16
PL_GPIO_15/B3	SSP2_CLK	UART3_RX	PWM0	PWM0	RMII0_RXD1	MII0_RXD2		GPIO_15
PL_GPIO_14/A2	SSP2_SS0	UART4_TX	PWM1	PWM1	RMII0_CRS_DV	MII0_RXD3		GPIO_14
PL_GPIO_13/A1	SSP2_MISO	UART4_RX	PWM2	PWM2	RMII0_RX_ER	MII0_COL		GPIO_13
PL_GPIO_12/D4	PWM3	0	PWM3	PWM3	SD_CD	MII0_CRS		GPIO_12
PL_GPIO_11/E5	Reserved	0	Reserved	Reserved	RMII_MDC	MII0_MDC		GPIO_11
PL_GPIO_10/C3	Reserved	0	Reserved	Reserved	RMII_MDIO	MII0_MDIO		GPIO_10
PL_GPIO_9/B2	0	UART3_TX	PWM0	0	I2C1_SDA	SSP0_MOSI		GPIO_9
PL_GPIO_8/C2	0	UART3_RX	PWM1	0	I2C1_SCL	SSP0_CLK		GPIO_8
PL_GPIO_7/D3	0	UART4_TX	PWM2	0	UART1_CTS	SSP0_SS0		GPIO_7
PL_GPIO_6/B1	0	UART4_RX	PWM3	0	UART1_DTR	SSP0_MISO		GPIO_6
PL_GPIO_5/D2	0	UART5_TX	0	0	UART1_RI	I2C0_SDA		GPIO_5
PL_GPIO_4/C1	0	UART5_RX	0	0	UART1_DCD	I2C0_SCL		GPIO_4
PL_GPIO_3/D1	I2C2_SDA	UART6_TX	0	0	UART1_DSR	UART0_RX		GPIO_3
PL_GPIO_2/E4	I2C2_SCL	UART6_RX	0	0	UART1_RTS	UART0_TX		GPIO_2
PL_GPIO_1/E3	UART2_TX	UART2_TX	UART2_TX	UART2_TX	I2C2_SDA	IrDA_RX		GPIO_1
PL_GPIO_0/F3	UART2_RX	UART2_RX	UART2_RX	UART2_RX	I2C2_SCL	IrDA_TX		GPIO_0
PL_CLK1/K17	CLCP	0	I2C1_SDA	SD_LED	UART3_TX	PL_CLK1		GPIO_98
PL_CLK2/J17	SD_CLK	SD_CLK	I2C1_SCL	SD_CLK	UART3_RX	PL_CLK2		GPIO_99

Table 15. PL_GPIO multiplexing scheme (continued)

PL_GPIO_# / ball number	Configuration mode (SW defined)					Alternate function (SW defined)	Boot pins	Function in GPIO alternative mode
	1	2	3	4	Extended			
PL_CLK3/J16	SD_WP	SD_WP	0	SD_WP	UART4_TX	PL_CLK3		GPIO_100
PL_CLK4/H17	SD_CMD	SD_CMD	0	SD_CMD	UART4_RX	PL_CLK4		GPIO_101

Note: 1 Table 15 cells filled with '0' or '1' are unused and unless otherwise configured as Alternate function or GPIO, the corresponding pin is held at low or high level respectively by the internal logic.

2 Pins shared by EMI and FSMC: Depending on the AHB address to be accessed the pins are used for EMI or FSMC transfers.

Table 16. Table shading

Shading	Pin group
FSMC	FSMC pins: NAND Flash
EMI	EMI pins
CLCD	Color LCD controller pins
Touchscreen	Touchscreen pins
UART	UART pins
CAN	CAN pins
Ethernet MAC	MII/RMII Ethernet MAC pins
SD/SDIO/MMC	SD card controller pins
PWM generators	Pulse-width modulator timer module pins
GPT	Timer pins
IrDa	IrDa pins
SSP	SSP pins
I2C	I2C pins
Standard Parallel port	Standard parallel port pins
I2S	I2S pins

3.4.7 Multiplexed signals description

This section provides a description of the multiplexed signals present in SPEAr320S device, grouped by IP.

Table 17. FSMC signals description

Signal name	Description	Dir.	PL_GPIO_# /Ball	Configuration mode
FSMC_ADDR_LE	Address latch enable (active high)	O	PL_GPIO_60/A14	1, 2, 3, 4
FSMC_CMD_ LE	Command latch enable (active high)	O	PL_GPIO_57/E11	1, 2, 3, 4
FSMC_CS0	Chip enable (active low)	O	PL_GPIO_55/A13	1, 2, 3, 4
FSMC_CS1			PL_GPIO_54/E10	1, 2, 3, 4
FSMC_CS2			PL_GPIO_53/D11	1, 2, 3, 4
FSMC_CS3			PL_GPIO_52/B12	1, 2, 3, 4
FSMC_D0	Data lines	IO	PL_GPIO_68/B15	1, 2, 3, 4
FSMC_D1			PL_GPIO_67/C14	1, 2, 3, 4
FSMC_D2			PL_GPIO_66/E13	1, 2, 3, 4
FSMC_D3			PL_GPIO_65/B14	1, 2, 3, 4
FSMC_D4			PL_GPIO_64/D13	1, 2, 3, 4
FSMC_D5			PL_GPIO_63/C13	1, 2, 3, 4
FSMC_D6			PL_GPIO_62/A15	1, 2, 3, 4
FSMC_D7			PL_GPIO_61/E12	1, 2, 3, 4
FSMC_D8			PL_GPIO_73/A17	3
FSMC_D9			PL_GPIO_72/B16	3
FSMC_D10			PL_GPIO_71/D14	3
FSMC_D11			PL_GPIO_70/C15	3
FSMC_D12			PL_GPIO_49/C11	3
FSMC_D13			PL_GPIO_48/B11	3
FSMC_D14			PL_GPIO_47/C10	3
FSMC_D15			PL_GPIO_46/A11	4
FSMC_RDY/BSY	Wait signal (active low)	I	PL_GPIO_56/C12	1, 2, 3, 4
FSMC_RE	Read enable (active low)	O	PL_GPIO_58/D12	1, 2, 3, 4
FSMC_WE	Write enable (active low)	O	PL_GPIO_59/B13	1, 2, 3, 4

Table 18. EMI signals description

Signal name	Description	Dir.	PL_GPIO_# /Ball	Configuration mode
EMI_A0	Address bus	O	PL_GPIO_97/H16	3
EMI_A1			PL_GPIO_96/H15	3
EMI_A2			PL_GPIO_95/H14	3
EMI_A3			PL_GPIO_94/H13	3
EMI_A4			PL_GPIO_93/G17	3
EMI_A5			PL_GPIO_92/G16	3
EMI_A6			PL_GPIO_91/G15	3
EMI_A7			PL_GPIO_90/G14	3
EMI_A8			PL_GPIO_89/F17	3
EMI_A9			PL_GPIO_88/F16	3
EMI_A10			PL_GPIO_87/G13	3
EMI_A11			PL_GPIO_86/E17	3
EMI_A12			PL_GPIO_85/F15	3
EMI_A13			PL_GPIO_84/D17	3
EMI_A14			PL_GPIO_83/E16	3
EMI_A15			PL_GPIO_82/E15	3
EMI_A16			PL_GPIO_81/C17	3
EMI_A17			PL_GPIO_80/D16	3
EMI_A18			PL_GPIO_79/F14	3
EMI_A19			PL_GPIO_78/D15	3
EMI_A20			PL_GPIO_77/B17	3
EMI_A21			PL_GPIO_76/F13	3
EMI_A22			PL_GPIO_75/E14	3
EMI_A23			PL_GPIO_74/C16	3
EMI_BYTEN0	Byte_enables are provided to validate the data present on the bus when high data is valid.	IO	PL_GPIO_51/D10	3
EMI_BYTEN1			PL_GPIO_50/A12	3
EMI_CE0	EMI Chip selects, derived from internal address decoding (kept disabled during NAND_Flash cycles)	O	PL_GPIO_55/A13	3
EMI_CE1			PL_GPIO_54/E10	3
EMI_CE2			PL_GPIO_53/D11	3
EMI_CE3			PL_GPIO_52/B12	3

Table 18. EMI signals description (continued)

Signal name	Description	Dir.	PL_GPIO_# /Ball	Configuration mode
EMI_D0	Data bus	O	PL_GPIO_68/B15	3
EMI_D1			PL_GPIO_67/C14	3
EMI_D2			PL_GPIO_66/E13	3
EMI_D3			PL_GPIO_65/B14	3
EMI_D4			PL_GPIO_64/D13	3
EMI_D5			PL_GPIO_63/C13	3
EMI_D6			PL_GPIO_62/A15	3
EMI_D7			PL_GPIO_61/E12	3
EMI_D8			PL_GPIO_73/A17	3
EMI_D9			PL_GPIO_72/B16	3
EMI_D10			PL_GPIO_71/D14	3
EMI_D11			PL_GPIO_70/C15	3
EMI_D12			PL_GPIO_49/C11	3
EMI_D13			PL_GPIO_48/B11	3
EMI_D14			PL_GPIO_47/C10	3
EMI_D15			PL_GPIO_46/A11	3
EMI_OE	Data output enable for read cycles, target device must open its data bus with this signal.	O	PL_GPIO_58/D12	3
EMI_WAIT	Transfer acknowledge signal, used by the cycle target to slow down the cycle (must be pulled up on the bus for targets that do not need it). *Note: This is an optional signal.*	I	PL_GPIO_69/A16	3
EMI_WE	Write strobe, data are ready on EMI_ADB before its falling edge and after the rising edge.	O	PL_GPIO_59/B13	3

Table 19. CLCD signals description

Signal name	Description	Dir.	PL_GPIO_# /Ball	Configuration mode
CLAC	STN AC bias drive or TFT data enable output	O	PL_GPIO_73/A17	1
CLCP	LCD panel clock	O	PL_CLK1/K17	1
CLD0	LCD panel data	O	PL_GPIO_97/H16	1
CLD1			PL_GPIO_96/H15	
CLD2			PL_GPIO_95/H14	
CLD3			PL_GPIO_94/H13	
CLD4			PL_GPIO_93/G17	
CLD5			PL_GPIO_92/G16	
CLD6			PL_GPIO_91/G15	
CLD7			PL_GPIO_90/G14	
CLD8			PL_GPIO_89/F17	
CLD9			PL_GPIO_88/F16	
CLD10			PL_GPIO_87/G13	
CLD11			PL_GPIO_86/E17	
CLD12			PL_GPIO_85/F15	
CLD13			PL_GPIO_84/D17	
CLD14			PL_GPIO_83/E16	
CLD15			PL_GPIO_82/E15	
CLD16			PL_GPIO_81/C17	
CLD17			PL_GPIO_80/D16	
CLD18			PL_GPIO_79/F14	
CLD19			PL_GPIO_78/D15	
CLD20			PL_GPIO_77/B17	
CLD21			PL_GPIO_76/F13	
CLD22			PL_GPIO_75/E14	
CLD23			PL_GPIO_74/C16	
CLFP	Frame pulse (STN)/ vertical synchronization pulse (TFT)	O	PL_GPIO_72/B16	1
CLLE	Line end signal	O	PL_GPIO_70/C15	1
CLLP	Line synchronization pulse (STN)/ horizontal synchronization pulse (TFT)	O	PL_GPIO_71/D14	1
CLPOWER	LCD panel power enable	O	PL_GPIO_69/A16	1

Table 20. Touchscreen signal description

Signal name	Description	Dir.	PL_GPIO_# /Ball	Configuration mode
TOUCHSCREEN X	Touchscreen select signal	O	PL_GPIO_36/C8	1

Table 21. UART signals description

Signal name	Description	Dir.	PL_GPIO_# /Ball	Configuration mode
UART0				
UART0_CTS	UART0 clear to send modem status input	I	PL_GPIO_38/A8	Alternate function
UART0_DCD	UART0 data carrier detect modem status input	I	PL_GPIO_39/A9	Alternate function
UART0_DSR	UART0 data set ready modem status input	I	PL_GPIO_40/B9	Alternate function
UART0_DTR	UART0 data terminal ready modem status output	O	PL_GPIO_42/D9	Alternate function
UART0_RI	UART0 ring indicator modem status input	I	PL_GPIO_41/C9	Alternate function
UART0_RTS	UART0 request to send modem status output	O	PL_GPIO_37/B8	Alternate function
UART0_RX	UART0 received serial data input	I	PL_GPIO_3/D1	Alternate function
UART0_TX	UART0 transmitted serial data output	O	PL_GPIO_2/E4	Alternate function
UART1				
UART1_CTS	UART1 clear to send modem status input	I	PL_GPIO_36/C8	3, 4
			PL_GPIO_85/F15	Extended mode
			PL_GPIO_7/D3	
UART1_DCD	UART1 data carrier detect modem status input	I	PL_GPIO_45/B10	3
			PL_GPIO_33/E7	4
			PL_GPIO_4/C1	Extended mode
			PL_GPIO_82/E15	
UART1_DSR	UART1 data set ready modem status input	I	PL_GPIO_44/A10	3
			PL_GPIO_32/D7	4
			PL_GPIO_3/D1	Extended mode
			PL_GPIO_81/C17	
UART1_DTR	UART1 data terminal ready modem status output	O	PL_GPIO_35/D8	3, 4
			PL_GPIO_84/D17	Extended mode
			PL_GPIO_6/B1	
UART1_RI	UART1 ring indicator modem status input	I	PL_GPIO_34/E8	3, 4
			PL_GPIO_83/E16	Extended mode
			PL_GPIO_5/D2	

Table 21. UART signals description (continued)

Signal name	Description	Dir.	PL_GPIO_# /Ball	Configuration mode
UART1_RTS	UART1 request to send modem status output	O	PL_GPIO_43/E9	3
			PL_GPIO_31/C7	4
			PL_GPIO_80/D16	Extended mode
			PL_GPIO_2/E4	
UART1_RX	UART1 received serial data input	I	PL_GPIO_28/A6	1, 2, 3, 4
UART1_TX	UART1 transmitted serial data output	O	PL_GPIO_29/A7	1, 2, 3, 4
UART2				
UART2_RX	UART2 received serial data input	I	PL_GPIO_0/F3	1, 2, 3, 4
UART2_TX	UART2 transmitted serial data output	O	PL_GPIO_1/E3	1, 2, 3, 4
UART3				
UART3_RX	UART3 received serial data input	I	PL_GPIO_15/B3	2
			PL_GPIO_8/C2	
			PL_GPIO_41/C9	3
			PL_GPIO_94/H13	4
			PL_GPIO_73/A17	Extended mode
			PL_GPIO_52/B12	
			PL_CLK2/J17	
UART3_TX	UART3 transmitted serial data output	O	PL_GPIO_16/E6	2
			PL_GPIO_9/B2	
			PL_GPIO_42/D9	3
			PL_GPIO_95/H14	4
			PL_GPIO_74/C16	Extended mode
			PL_GPIO_53/D11	
			PL_CLK1/K17	
UART4				
UART4_RX	UART4 received serial data input	I	PL_GPIO_13/A1	2
			PL_GPIO_6/B1	
			PL_GPIO_39/A9	3
			PL_GPIO_92/G16	4
		I	PL_GPIO_71/D14	Extended mode
			PL_CLK4/H17	

Table 21. UART signals description (continued)

Signal name	Description	Dir.	PL_GPIO_# /Ball	Configuration mode
UART4_TX	UART4 transmitted serial data output	O	PL_GPIO_14/A2	2
			PL_GPIO_7/D3	
			PL_GPIO_40/B9	3
			PL_GPIO_93/G17	4
			PL_GPIO_72/B16	Extended mode
			PL_CLK3/J16	
UART5				
UART5_RX	UART5 received serial data input	I	PL_GPIO_4/C1	2
			PL_GPIO_37/B8	3
			PL_GPIO_90/G14	4
			PL_GPIO_69/A16	Extended mode
UART5_TX	UART5 transmitted serial data output	O	PL_GPIO_5/D2	2
			PL_GPIO_38/A8	3
			PL_GPIO_91/G15	4
			PL_GPIO_70/C15	Extended mode
UART6				
UART6_RX	UART6 received serial data input	I	PL_GPIO_2/E4	2
			PL_GPIO_88/F16	4
UART6_TX	UART6 transmitted serial data output	O	PL_GPIO_3/D1	2
			PL_GPIO_89/F17	4
UART/RS485				
UART_RS485_TX	UART/RS485 transmitted serial data output	O	PL_GPIO_79/F14	Extended mode
UART_RS485_RX	UART/RS485 received serial data output	I	PL_GPIO_78/D15	Extended mode
UART_RS485_OE	UART/RS485 data output enable	O	PL_GPIO_77/B17	Extended mode

Table 22. CAN signals description

Signal name	Description	Dir.	PL_GPIO_# /Ball	Configuration mode
CAN0				
CAN0_RX	CAN0 receiver data input	I	PL_GPIO_32/D7	1, 2, 3
CAN0_TX	CAN0 transmitter data output	O	PL_GPIO_33/E7	1, 2, 3
CAN1				
CAN1_RX	CAN1 receiver data input	I	PL_GPIO_30/B7	1, 2, 3
CAN1_TX	CAN1 transmitter data output	O	PL_GPIO_31/C7	1, 2, 3

Table 23. MMC-SD/SDIO controller signals description

Signal name	Description	Dir.	PL_GPIO_# /Ball	Configuration mode
SD_CD	Card detection for single slot (active low)	I	PL_GPIO_51/D10	1, 2, 4
			PL_GPIO_12/D4	Extended mode
SD_CLK	Clock to external card	O	PL_CLK2/J17	1, 2, 4
SD_CMD	Command line	IO	PL_CLK4/H17	1, 2, 4
SD_DAT0	Data line	IO	PL_GPIO_43/E9	1, 2, 4
SD_DAT1			PL_GPIO_44/A10	1, 2, 4
SD_DAT2			PL_GPIO_45/B10	1, 2, 4
SD_DAT3			PL_GPIO_46/A11	1, 2, 4
SD_DAT4			PL_GPIO_47/C10	1, 2, 4
SD_DAT5			PL_GPIO_48/B11	1, 2, 4
SD_DAT6			PL_GPIO_49/C11	1, 2, 4
SD_DAT7			PL_GPIO_50/A12	1, 2, 4
SD_LED	Cautions the user not to remove the card while the SD card is being accessed.	O	PL_GPIO_34/E8	1, 2
			PL_CLK1/K17	4
SD_WP	SD card write protect (active low)	I	PL_CLK3/J16	1, 2, 4

Table 24. PWM signals description

Signal name	Description	Dir.	PL_GPIO_# /Ball	Configuration mode
PWM0	PWM0 output channel	O	PL_GPIO_38/A8	1, 2
			PL_GPIO_15/B3	3, 4
			PL_GPIO_9/B2	3
			PL_GPIO_89/F17	Extended mode
			PL_GPIO_60/A14	
			PL_GPIO_43/E9	
			PL_GPIO_31/C7	
PWM1	PWM1 output channel	O	PL_GPIO_37/B8	1, 2
			PL_GPIO_14/A2	3, 4
			PL_GPIO_8/C2	3
			PL_GPIO_88/F16	Extended mode
			PL_GPIO_59/B13	
			PL_GPIO_42/D9	
			PL_GPIO_30/B7	

Table 24. PWM signals description (continued)

Signal name	Description	Dir.	PL_GPIO_# /Ball	Configuration mode
PWM2	PWM2 output channel	O	PL_GPIO_34/E8	1, 2
			PL_GPIO_13/A1	3, 4
			PL_GPIO_7/D3	3
			PL_GPIO_87/G13	Extended mode
			PL_GPIO_58/D12	
			PL_GPIO_41/C9	
			PL_GPIO_29/A7	
PWM3	PWM3 output channel	O	PL_GPIO_12/D4	1, 3, 4
			PL_GPIO_6/B1	3
			PL_GPIO_86/E17	Extended mode
			PL_GPIO_57/E11	
			PL_GPIO_40/B9	
			PL_GPIO_28/A6	

Table 25. GPT signals description

Signal name	Description	Dir.	PL_GPIO_# /Ball	Configuration mode
TMR_CLK1	This clock toggles each time the timer interrupt goes active.	O	PL_GPIO_43/E9	Alternate function
TMR_CLK2			PL_GPIO_44/A10	Alternate function
TMR_CLK3			PL_GPIO_45/B10	Alternate function
TMR_CLK4			PL_GPIO_46/A11	Alternate function
TMR_CPTR1	Asynchronous signal provided for the measurement of timing signals	I	PL_GPIO_47/C10	Alternate function
TMR_CPTR2			PL_GPIO_48/B11	Alternate function
TMR_CPTR3			PL_GPIO_49/C11	Alternate function
TMR_CPTR4			PL_GPIO_50/A12	Alternate function

Table 26. IrDA signals description

Signal name	Description	Dir.	PL_GPIO_# /Ball	Configuration mode
IrDA_RX	IrDA receiver data input	I	PL_GPIO_1/E3	Alternate function
IrDA_TX	IrDA transmitter data output	O	PL_GPIO_0/F3	Alternate function

Table 27. SSP signals description

Signal name	Description	Dir.	PL_GPIO_# /Ball	Configuration mode
SSP0				
SSP0_CS2	Slave select (used only in master mode)	O	PL_GPIO_34/E8	Alternate function
SSP0_CS3	Slave select (used only in master mode)	O	PL_GPIO_35/D8	Alternate function
SSP0_CS4	Slave select (used only in master mode)	O	PL_GPIO_36/C8	Alternate function
SSP0_CLK	SSP clock. It is used as output in master mode as input in slave mode.	IO	PL_GPIO_8/C2	Alternate function
SSP0_MISO	Master input slave output	IO	PL_GPIO_6/B1	Alternate function
SSP0_MOSI	Master output slave input	IO	PL_GPIO_9/B2	Alternate function
SSP0_SS0	SSP frame output (master mode), input (slave mode)	IO	PL_GPIO_7/D3	Alternate function
SSP1				
SSP1_CLK	SSP clock. It is used as output in master mode as input in slave mode.	IO	PL_GPIO_19/A3	1, 4
			PL_GPIO_96/H15	Extended mode
			PL_GPIO_67/C14	
			PL_GPIO_50/A12	
			PL_GPIO_38/A8	
SSP1_MISO	Master input slave output	IO	PL_GPIO_17/C4	1, 4
			PL_GPIO_94/H13	Extended mode
			PL_GPIO_65/B14	
			PL_GPIO_48/B11	
			PL_GPIO_36/C8	
SSP1_MOSI	Master output slave input	IO	PL_GPIO_20/B4	1, 4
			PL_GPIO_97/H16	Extended mode
			PL_GPIO_68/B15	
			PL_GPIO_51/D10	
			PL_GPIO_39/A9	
SSP1_SS0	SSP frame output (master mode), input (slave mode)	IO	PL_GPIO_18/D5	1, 4
			PL_GPIO_95/H14	Extended mode
			PL_GPIO_66/E13	
			PL_GPIO_49/C11	
			PL_GPIO_37/B8	
SSP2				

Table 27. SSP signals description (continued)

Signal name	Description	Dir.	PL_GPIO_# /Ball	Configuration mode
SSP2_CLK	SSP clock. It is used as output in master mode as input in slave mode.	IO	PL_GPIO_15/B3	1
			PL_GPIO_92/G16	Extended mode
			PL_GPIO_63/C13	
			PL_GPIO_46/A11	
			PL_GPIO_34/E8	
SSP2_MISO	Master input slave output	IO	PL_GPIO_13/A1	1
			PL_GPIO_90/G14	Extended mode
			PL_GPIO_61/E12	
			PL_GPIO_44/A10	
			PL_GPIO_32/D7	
SSP2_MOSI	Master output slave input	IO	PL_GPIO_16/E6	1
			PL_GPIO_47/C10	Extended mode
			PL_GPIO_35/D8	
			PL_GPIO_16/E6	
			PL_GPIO_93/G17	
			PL_GPIO_64/D13	
SSP2_SS0	SSP frame output (master mode), input (slave mode)	IO	PL_GPIO_14/A2	1
			PL_GPIO_91/G15	Extended mode
			PL_GPIO_62/A15	
			PL_GPIO_45/B10	
			PL_GPIO_33/E7	

Table 28. I2C signals description

Signal name	Description	Dir.	PL_GPIO_# /Ball	Configuration mode
I2C0				
I2C0_SCL	I2C0 input/output clock	IO	PL_GPIO_4/C1	Alternate function
I2C0_SDA	I2C0 input/output data	IO	PL_GPIO_5/D2	Alternate function
I2C1				
I2C1_SCL	I2C1 input/output clock	IO	PL_CLK2/J17	3
			PL_GPIO_8/C2	Extended mode
I2C1_SDA	I2C1 input/output data	IO	PL_CLK1/K17	3
			PL_GPIO_9/B2	Extended mode
I2C2				
I2C2_SCL	I2C2 input/output clock	IO	PL_GPIO_2/E4	1
			PL_GPIO_19/A3	2
			PL_GPIO_96/H15	4
			PL_GPIO_75/E14	Extended mode
			PL_GPIO_0/F3	
I2C2_SDA	I2C2 input/output data	IO	PL_GPIO_3/D1	1
			PL_GPIO_20/B4	2
			PL_GPIO_97/H16	4
			PL_GPIO_76/F13	Extended mode
			PL_GPIO_1/E3	

Table 29. I2S signals description

Signal name	Description	Dir.	PL_GPIO_# /Ball	Configuration mode
audio_over_samp_clk	Audio oversampling clock. This is the clock that I2S_CLK derives from. The interfacing digital-to-analog converter (DAC) can use this clock to (over)sample the I2S data.	O	PL_GPIO_35/D8	1, 2
I2S_CLK	I2S clock	O	PL_GPIO_39/A9	1, 2
I2S_LR	I2S word select	O	PL_GPIO_40/B9	1, 2
I2S_RX	I2S receive data	I	PL_GPIO_42/D9	1, 2
I2S_TX	I2S transmit data	O	PL_GPIO_41/C9	1, 2

Table 30. SPP signals description

Signal name	Description	Dir.	PL_GPIO_# /Ball	Configuration mode
SPP_ACKn	The peripheral pulses this line low when it has received the previous data and is ready to receive more data. The rising edge of SPP_ACKn can be enabled to interrupt the host.	O	PL_GPIO_76/F13	4
SPP_AUTOFDn	Usage of this line varies. Most printers will perform a line feed after each carriage return when this line is low, and carriage returns only when this line is high.	I	PL_GPIO_72/B16	4
SPP_BUSY	The peripheral drives this signal high to indicate that it is not ready to receive data.	O	PL_GPIO_75/E14	4
SPP_DATA0	SPP unidirectional data lines	O	PL_GPIO_85/F15	4
SPP_DATA1			PL_GPIO_84/D17	4
SPP_DATA2			PL_GPIO_83/E16	4
SPP_DATA3			PL_GPIO_82/E15	4
SPP_DATA4			PL_GPIO_81/C17	4
SPP_DATA5			PL_GPIO_80/D16	4
SPP_DATA6			PL_GPIO_79/F14	4
SPP_DATA7			PL_GPIO_78/D15	4
SPP_FAULTn	Usage of this line varies. Peripherals usually drive this line low when an error condition exists.	O	PL_GPIO_71/D14	4
SPP_INITn	This line is held low for a minimum of 50 µs to reset the printer and clear the print buffer.	I	PL_GPIO_70/C15	4
SPP_PERROR	Usage of this line varies. Printers typically drive this signal high during a paper empty condition.	O	PL_GPIO_74/C16	4
SPP_SELECT	The peripheral drives this signal high when it is selected and ready for data transfer.	O	PL_GPIO_73/A17	4
SPP_SELINn	The host drives this line low to select the peripheral.	I	PL_GPIO_69/A16	4
SPP_STRBn	Data is valid during an active low pulse on this line.	I	PL_GPIO_77/B17	4

Table 31. Ethernet signals description

Signal name	Description	Dir.	PL_GPIO_# / ball number	Configuration mode (see *Section 3.4.2*)
MII0				
MII0_COL	PHY collision This signal is asserted by the PHY when a collision is detected on the medium. This signal is not synchronous to any clock. (Active high)	I	PL_GPIO_13/A1	Alternate function
MII0_CRS	PHY CRS This signal is asserted by the PHY when either the transmit or receive medium is not idle. The PHY deasserts this signal when both transmit and receive medium are idle. This signal is not synchronous to any clock. (Active high)	I	PL_GPIO_12/D4	Alternate function
MII0_MDC	Management data clock The MAC provides timing reference for the MAC_MDIO signal through this aperiodic clock. The maximum frequency of this clock is 2.5 MHz.This clock is generated from the application clock (HCLK) via a clock divider.	O	PL_GPIO_11/E5	Alternate function
MII0_MDIO	Management data input/output	IO	PL_GPIO_10/C3	Alternate function
MII0_RXCLK	Reception clock This is the reception clock (25/2.5 MHz in 100M/10Mbps) provided by the external PHY for MII interfaces. The MII0_RXDn signals that the Ethernet controller receives are synchronous to this clock.	I	PL_GPIO_20/B4	Alternate function
MII0_RXD0	PHY receive data These bits provide the MII receive data nibble. The validity of the data is qualified with MII0_RXDV and MII0_RXER.	I	PL_GPIO_17/C4	Alternate function
MII0_RXD1			PL_GPIO_16/E6	Alternate function
MII0_RXD2			PL_GPIO_15/B3	Alternate function
MII0_RXD3			PL_GPIO_14/A2	Alternate function
MII0_RXDV	PHY receive data valid When high, indicates that the data on the MII0_RXDn bus is valid. It remains asserted continuously from the first recovered byte/nibble of the frame through the final recovered byte/nibble.	I	PL_GPIO_19/A3	Alternate function
MII0_RXER	PHY receive error When high, indicates an error or carrier extension in the received frame on the MII0_RXDn bus.	I	PL_GPIO_18/D5	Alternate function

Table 31. Ethernet signals description (continued)

Signal name	Description	Dir.	PL_GPIO_# / ball number	Configuration mode (see *Section 3.4.2*)
MII0_TXCLK	Transmission clock This is the transmission clock (25/2.5 MHz in 100 M/10 Mbps) provided by the external PHY for the MII interface. All the MII0_TXDn signals generated by the MAC are synchronous to this clock.	I	PL_GPIO_27/B6	Alternate function
MII0_TXD0	PHY transmit data. These bits provide the MII transmit data nibble. The validity of the data is qualified with MII0_TXEN and MII0_TXER.	O	PL_GPIO_26/A5	Alternate function
MII0_TXD1			PL_GPIO_25/C6	Alternate function
MII0_TXD2			PL_GPIO_24/B5	Alternate function
MII0_TXD3			PL_GPIO_23/A4	Alternate function
MII0_TXEN	PHY transmit data enable When high, it indicates that valid data is being transmitted on the MII0_TXDn bus.	O	PL_GPIO_22/D6	Alternate function
MII0_TXER	PHY transmit error When high, indicates a transmit error or carrier extension on the MII0_RXDn bus.	O	PL_GPIO_21/C5	Alternate function
MII1				
MII1_COL	PHY collision This signal is asserted by the PHY when a collision is detected on the medium. This signal is not synchronous to any clock. (Active high)	I	PL_GPIO_83/E16	2
MII1_CRS	PHY CRS This signal is asserted by the PHY when either the transmit or receive medium is not idle. The PHY deasserts this signal when both transmit and receive medium are idle. This signal is not synchronous to any clock. (Active high)	I	PL_GPIO_82/E15	2
MII1_MDC	Management data clock The MAC provides timing reference for the MII1_MDIO signal through this aperiodic clock. The maximum frequency of this clock is 2.5 MHz.This clock is generated inside the Ethernet controller from the application clock (HCLK) via a clock divider.	O	PL_GPIO_80/D16	2
MII1_MDIO	Management data input/output	IO	PL_GPIO_81/C17	2
MII1_RXCLK	This is the reception clock (25/2.5 MHz in 100M/10Mbps) provided by the external PHY for MII interfaces. All MII1_RXDn signals that the Ethernet controller receives are synchronous to this clock.	I	PL_GPIO_90/G14	2

Table 31. Ethernet signals description (continued)

Signal name	Description	Dir.	PL_GPIO_# / ball number	Configuration mode (see *Section 3.4.2*)
MII1_RXD0	PHY receive data These bits provide the MII receive data nibble. The validity of the data is qualified with MII1_RXDV and MII1_RXER.	I	PL_GPIO_87/G13	2
MII1_RXD1			PL_GPIO_86/E17	2
MII1_RXD2			PL_GPIO_85/F15	2
MII1_RXD3			PL_GPIO_84/D17	2
MII1_RXDV	PHY receive data valid When high, indicates that the data on the MII1_RXDn bus is valid. It remains asserted continuously from the first recovered byte/nibble of the frame through the final recovered byte/nibble.	I	PL_GPIO_89/F17	2
MII1_RXER	PHY receive error When high, indicates an error or carrier extension in the received frame on the MII1_RXDn bus.	I	PL_GPIO_88/F16	2
MII1_TXCLK	Transmission clock This is the transmission clock (25/2.5 MHz in 100M/10Mbps) provided by the external PHY for the MII. All the MII transmission signals generated by the MAC are synchronous to this clock.	I	PL_GPIO_97/H16	2
MII1_TXD0	PHY transmit data. These bits provide the MII transmit data nibble. The validity of the data is qualified with MII1_TXEN and MII1_TXER.	O	PL_GPIO_96/H15	2
MII1_TXD1			PL_GPIO_95/H14	2
MII1_TXD2			PL_GPIO_94/H13	2
MII1_TXD3			PL_GPIO_93/G17	2
MII1_TXEN	PHY transmit data enable When high, indicates that valid data is being transmitted on the MII1_TXDn bus.	O	PL_GPIO_92/G16	2
MII1_TXER	PHY transmit error When high, indicates a transmit error or carrier extension on the MII1_RXDn bus.	O	PL_GPIO_91/G15	2
RMII0/RMII1				
RMII_MDC	Management data clock The MAC provides timing reference for the RMII_MDIO signal through this aperiodic clock. The maximum frequency of this clock is 2.5 MHz.This clock is generated from the application clock (HCLK) via a clock divider.	O	PL_GPIO_11/E5	Extended mode
RMII_MDIO	Management data input/output	IO	PL_GPIO_10/C3	Extended mode
RMII_REF_CLK	50 MHz reference clock input for RMII interface	I	PL_GPIO_22/D6	Extended mode

Table 31. Ethernet signals description (continued)

Signal name	Description	Dir.	PL_GPIO_# / ball number	Configuration mode (see *Section 3.4.2*)
RMII0_CRS_DV	PHY receive data valid Contains the CRS (carrier sense) and data valid information of the receive interface.	I	PL_GPIO_14/A2	Extended mode
RMII0_RX_ER	PHY receive error	I	PL_GPIO_13/A1	Extended mode
RMII0_RXD0	PHY receive data These bits provide the RMII receive data. The validity of the data is qualified with RMII0_CRS_DV.	I	PL_GPIO_26/A5	Extended mode
RMII0_RXD1			PL_GPIO_15/B3	Extended mode
RMII0_TX_EN	PHY transmit data enable When high, indicates that valid data is being transmitted on the RMII_TXDn bus	O	PL_GPIO_16/E6	Extended mode
RMII0_TXD0	PHY transmit data These bits provide the RMII transmit data. The validity of the data is qualified with RMII0_TX_EN.	O	PL_GPIO_27/B6	Extended mode
RMII0_TXD1			PL_GPIO_17/C4	Extended mode
RMII1_CRS_DV	PHY receive data valid Contains the crs and data valid information of the receive interface.	I	PL_GPIO_19/A3	Extended mode
RMII1_RX_ER	PHY receive error	I	PL_GPIO_18/D5	Extended mode
RMII1_RXD0	PHY receive data These bits provide the RMII receive data. The validity of the data is qualified with RMII1_CRS_DV.	I	PL_GPIO_24/B5	Extended mode
RMII1_RXD1			PL_GPIO_20/B4	Extended mode
RMII1_TX_EN	PHY transmit data enable When high, it indicates that valid data is being transmitted on the RMII_TXDn bus.	O	PL_GPIO_23/A4	Extended mode
RMII1_TXD0	PHY transmit data These bits provide the RMII transmit data. The validity of the data is qualified with RMII1_TX_EN.	O	PL_GPIO_25/C6	Extended mode
RMII1_TXD1			PL_GPIO_21/C5	Extended mode

3.5 PL_GPIO pin sharing for debug modes

In some cases the PL_GPIO pins may be used in different ways for debugging purposes. There are three different cases (see also *Table 32*):

1. Case 1 - All the PL_GPIO get values from Boundary scan registers during Ex-test instruction of JTAG . Typically, this configuration is used to verify the correctness of the soldering process during the production flow.
2. Case 2 - All the PL_GPIO maintain their original meaning but the JTAG Interface is connected to the processor. This configuration is useful during the development phase, but offers only “static” debug.
3. Case 3 - Some PL_GPIOs, as shown in *Table 32* below, are used to connect the ETM9 lines to an external box. This configuration is typically used only during the development phase. It offers a very powerful debug capability. When the processor reaches a breakpoint it is possible, by analyzing the trace buffer, to understand the reason why the processor has reached the break.

Table 32. Ball sharing during debug

Signals	Case 1 - no debug	Case 2 - static debug	Case 3 - full debug
TEST_0	0	1	0
TEST_1	0	0	1
TEST_2	0	0/1	0/1
TEST_3	0	0/1	0/1
TEST_4	1	0/1	0/1
nTRST	nTRST_bscan	nTRST_ARM	nTRST_ARM
TCK	TCK_bscan	TCK_ARM	TCK_ARM
TMS	TSM_bscan	TMS_ARM	TSM_ARM
TDI	TDI_bscan	TDI_ARM	TDI_ARM
TDO	TDO_bscan	TDO_ARM	TDO_ARM
PL_GPIO_97	BSR Value	Original meaning	ARM_TRACE_CLK
PL_GPIO_96	BSR Value	Original meaning	ARM_TRACE_PKTA[0]
PL_GPIO_95	BSR Value	Original meaning	ARM_TRACE_PKTA[1]
PL_GPIO_94	BSR Value	Original meaning	ARM_TRACE_PKTA[2]
PL_GPIO_93	BSR Value	Original meaning	ARM_TRACE_PKTA[3]
PL_GPIO_92	BSR Value	Original meaning	ARM_TRACE_PKTB[0]
PL_GPIO_91	BSR Value	Original meaning	ARM_TRACE_PKTB[1]
PL_GPIO_90	BSR Value	Original meaning	ARM_TRACE_PKTB[2]
PL_GPIO_89	BSR Value	Original meaning	ARM_TRACE_PKTB[3]
PL_GPIO_88	BSR Value	Original meaning	ARM_TRACE_SYNCA
PL_GPIO_87	BSR Value	Original meaning	ARM_TRACE_SYNCB
PL_GPIO_86	BSR Value	Original meaning	ARM_PIPESTATA[0]
PL_GPIO_85	BSR Value	Original meaning	ARM_PIPESTATA[1]

Table 32. Ball sharing during debug (continued)

Signals	Case 1 - no debug	Case 2 - static debug	Case 3 - full debug
PL_GPIO_84	BSR Value	Original meaning	ARM_PIPESTATA[2]
PL_GPIO_83	BSR Value	Original meaning	ARM_PIPESTATB[0]
PL_GPIO_82	BSR Value	Original meaning	ARM_PIPESTATB[1]
PL_GPIO_81	BSR Value	Original meaning	ARM_PIPESTATB[2]
PL_GPIO_80	BSR Value	Original meaning	ARM_TRACE_PKTA[4]
PL_GPIO_79	BSR Value	Original meaning	ARM_TRACE_PKTA[5]
PL_GPIO_78	BSR Value	Original meaning	ARM_TRACE_PKTA[6]
PL_GPIO_77	BSR Value	Original meaning	ARM_TRACE_PKTA[7]
PL_GPIO_76	BSR Value	Original meaning	ARM_TRACE_PKTB[4]
PL_GPIO_75	BSR Value	Original meaning	ARM_TRACE_PKTB[5]
PL_GPIO_74	BSR Value	Original meaning	ARM_TRACE_PKTB[6]
PL_GPIO_73	BSR Value	Original meaning	ARM_TRACE_PKTB[7]
PL_GPIO_[72:0]			

4 Electrical characteristics

4.1 Absolute maximum ratings

This product contains devices to protect the inputs against damage due to high/low static voltages. However, it is advisable to take normal precaution to avoid application of any voltage higher/lower than the specified maximum/minimum rated voltages.

Caution: Stresses above those listed in *Table 33* may cause permanent damage to the device. Exposure to maximum rating conditions for extended periods may affect device reliability.

Table 33. Absolute maximum ratings

Symbol	Parameter	Min	Max	Unit
V_{DD} 1.2	Supply voltage for the core	- 0.3	1.44	V
V_{DD} 3.3	Supply voltage for the I/Os	- 0.3	3.9	V
V_{DD} 2.5	Supply voltage for the analog blocks	- 0.3	3	V
V_{DD} 1.8	Supply voltage for the DRAM interface	- 0.3	2.16	V
V_{DD} RTC	RTC supply voltage	-0.3	2.16	V
T_{STG}	Storage temperature	-55	150	°C

4.2 Maximum power consumption

Note: These values take into consideration the worst cases of process variation and voltage range and must be used to design the power supply section of the board.

Table 34. Maximum power consumption

Symbol	Description	Max	Unit
$I_{DD(1.2Vsupply)}$	Current consumption of V_{DD} 1.2 supply voltage for the core	400	mA
$I_{DD(1.8Vsupply)}$	Current consumption of V_{DD} 1.8 supply voltage for the DRAM interface (1)	150	mA
$I_{DD(RTC)}$	Current consumption of RTC supply voltage	8	µA
$I_{DD(2.5Vsupply)}$	Current consumption of 2.5V supply voltage for the analog blocks	30	mA
$I_{DD(3.3Vsupply)}$	Current consumption of 3.3V supply voltage for the I/Os(2)	12	mA
P_D	Maximum power consumption(3)	870	mW

1. Peak current with Linux memory test (50% write and 50% read) plus DMA reading memory.
2. With 30 logic channels connected to the device and simultaneously switching at 10 MHz.
3. Based on bench measurements for worst case silicon under worst case operating conditions. Devices tested with operating system running, CPU and DDR2 running at 333 MHz, DDR2 driven by PLL2, SDRAM and all on-chip peripherals and internal modules enabled.

   1.2 V current and power are primarily dependent on the applications running and the use of internal chip functions (DMA, USB, Ethernet, and so on).

   3.3 V current and power are primarily dependent on the capacitive loading, frequency, and utilization of the external buses.

4.3 Recommended operating conditions

To ensure proper operation of the device, it is highly recommended to follow the conditions shown in the following table.

Table 35. Recommended operating conditions

Symbol	Parameter	Min	Typ	Max	Unit
V_{DD} 1.2	Supply voltage for the core	1.14	1.2	1.3	V
V_{DD} 3.3	Supply voltage for the I/Os	3	3.3	3.6	V
V_{DD} 2.5	PLL supply voltage(1)	2.25	2.5	2.75	V
V_{DD} 2.5	Oscillator supply voltage	2.25	2.5	2.75	V
V_{DD} 1.8	Supply voltage for DRAM interface	1.70	1.8	1.9	V
V_{DD} RTC	RTC supply voltage	1.3	1.5	1.8	V
T_A	Ambient temperature(2)	-40	–	85	°C
T_J	Junction temperature	-40	–	125	°C

1. For power supply filtering it is required to add an external ferrite inductor.
2. T_A to be considered under JESD51 conditions or equivalent ones.

4.4 Overshoot and undershoot

This product can support the following values of overshoot and undershoot.

Table 36. Overshoot and undershoot specifications

Parameter	3V3 I/Os	2V5 I/Os	1V8 I/Os
Amplitude	500 mV	500 mV	500 mV
Ratio of overshoot (or undershoot) duration with respect to pulse width	1/3	1/3	1/3

If the amplitude of the overshoot/undershoot increases (decreases), the ratio of overshoot/undershoot width to the pulse width decreases (increases). The formula relating the two is:

Amplitude of OS/US = 0.75*(1- ratio of OS (or US) duration with respect to pulse width)

Note: The value of overshoot/undershoot should not exceed the value of 0.5 V. However, the duration of the overshoot/undershoot can be increased by decreasing its amplitude.

4.5 3.3V I/O characteristics

The 3.3 V I/Os are compliant with JEDEC standard JESD8b.

Table 37. Low voltage TTL DC input specification (3 V< V_{DD} <3.6 V)

Symbol	Parameter	Min	Max	Unit
V_{IL}	Low level input voltage		0.8	V
V_{IH}	High level input voltage	2		V
V_{hyst}	Schmitt trigger hysteresis	300	800	mV

Table 38. Low voltage TTL DC output specification (3 V< V_{DD} <3.6 V)

Symbol	Parameter	Test condition	Min	Max	Unit
V_{OL}	Low level output voltage	I_{OL}= X mA (1)		0.3	V
V_{OH}	High level output voltage	I_{OH}= -X mA (1)	V_{DD} - 0.3		V

1. Maximum current load (IOL) = 10 mA for PL_GPIO and PL_CLK pins. For the IOL max value of dedicated pins, refer to *Chapter 3: Pin description*.

Table 39. Pull-up and pull-down characteristics

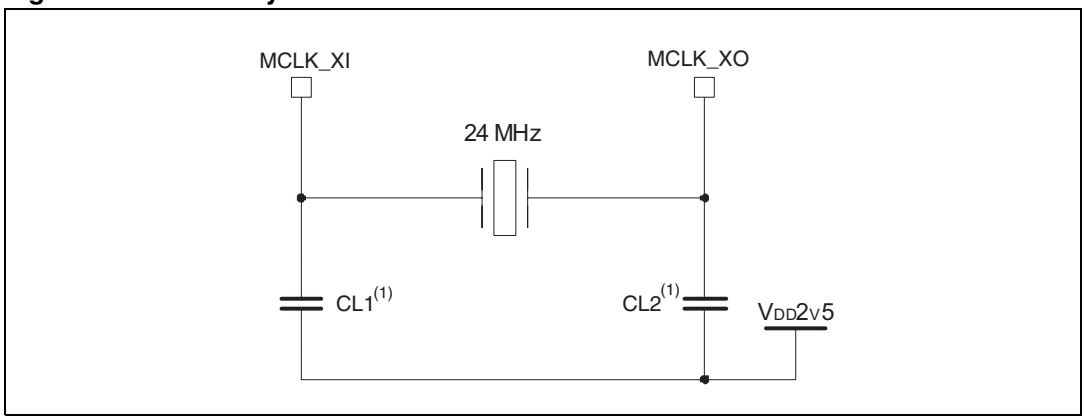
Symbol	Parameter	Test condition	Min	Max	Unit
R_{PU}	Equivalent pull-up resistance	V_I = 0 V	29	67	kΩ
R_{PD}	Equivalent pull-down resistance	V_I = V_{DDE}3V3	29	103	kΩ

4.6 Clocking parameters

4.6.1 Master clock (MCLK)

External clock generated from a crystal oscillator

Figure 4. MCLK crystal connection



1. CL1 and CL2 are the load capacitors.

The value of the capacitors depends on the type of the selected crystal. To calculate the value of the load capacitance, use the formula given below.

For this example, Aker C2E-24.000-12-3030-X 24 MHz oscillator has been used.

Formula

$$CL = (CL1*CL2 / CL1+CL2) + CS$$

Where CL1 and CL2 are the load capacitors and CS is the circuit stray capacitance.

In our application:

$$CL1 = CL2 = Cext$$

This implies:

$$Cext = (CL-CS)*2$$

Example:

For the Aker C2E-24.000-12-3030-X crystal, CL = 12 PF

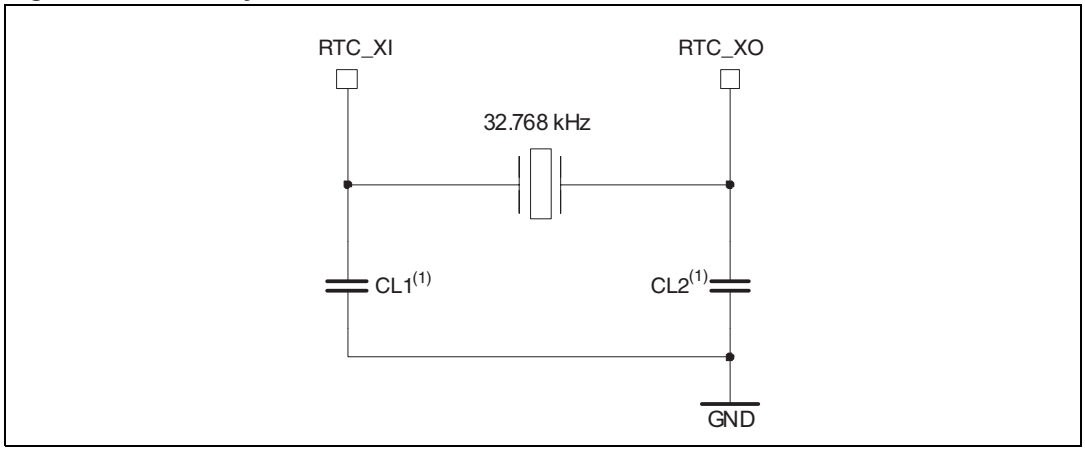
With CS = 3 PF, we have: Cext = CL1 = CL2 = 18 PF

Note: The ESR of the used quarz must be < 50 Ohm.

4.6.2 Real-time clock (RTC)

External clock generated from a crystal oscillator

Figure 5. RTC crystal connection



1. CL1 and CL2 are the load capacitors.

The value of the capacitors depends on the type of the selected crystal. For example, using Fox Electronics, P/N NC26LF-327 32.768 KHz oscillator, the value of the capacitors is 15 pF. The oscillator may not start if we use the crystal Fox fx325bs.

If the shunt capacitance (Co) of the crystal is ~7.0 pF, then the maximum ESR of the crystal must be less than 50 Ohms.

4.7 LPDDR and DDR2 pin characteristics

Table 40. DC characteristics

Symbol	Parameter	Test condition	Min	Max	Unit
V_{IL}	Low level input voltage	SSTL18	-0.3	V_{REF}-0.125	V
V_{IH}	High level input voltage	SSTL18	V_{REF}+0.125	V_{DDE}1V8+0.3	V
V_{hyst}	Input voltage hysteresis		200		mV

Table 41. Driver characteristics

Symbol	Parameter	Min	Typ	Max	Unit
R_O	Output impedance		45		Ω

Table 42. On-die termination

Symbol	Parameter	Min	Typ	Max	Unit
RT1	Termination value of resistance for on die termination		75		Ω
RT2	Termination value of resistance for on die termination		150		Ω

Table 43. Reference voltage

Symbol	Parameter	Min	Typ	Max	Unit
V_{REFIN}	Voltage applied to core/pad	0.49 * V_{DDE}	0.500 * V_{DDE}	0.51 * V_{DDE}	V

4.8 ADC pin characteristics

Table 44. ADC pin characteristics

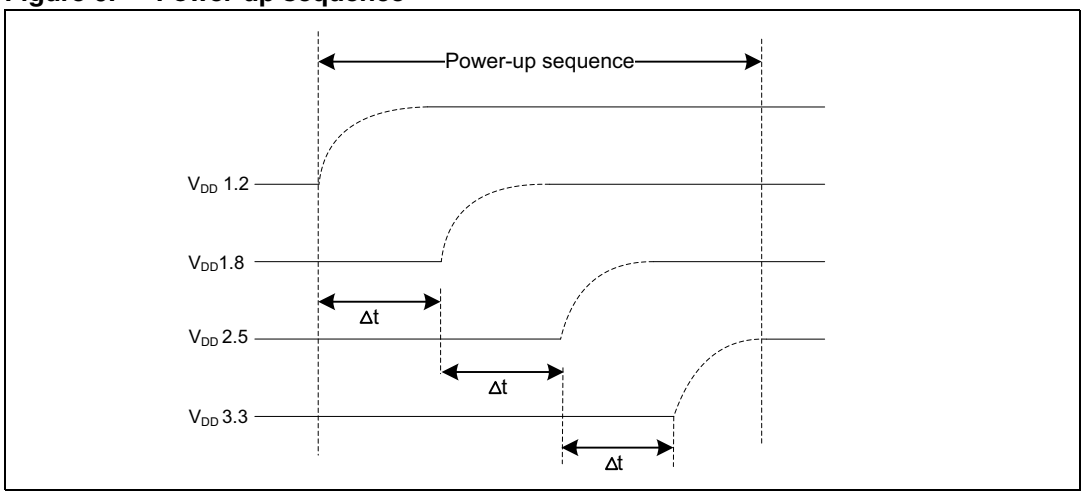
Symbol	Parameters	Min	Typ	Max	Unit
f_{ADC_CLK}	ADC_CLK frequency	3		14	MHz
AV_{DD}	ADC supply voltage			2.5	V
V_{REFP}	Positive reference voltage			2.5	V
V_{REFN}	Negative reference voltage	0			V
V_{IREF}	Internal reference voltage	1.95	2	2.05	V
$t_{STARTUP}$	Startup time		50		µs
V_{AIN}	Input range (absolute)	AGND - 0.3		AVDD - 0.3	V
	Conversion range	V_{REFN}		V_{REFP}	V
C_{AIN}	Input capacitance	5	6.4	8	pF
R_{AIN}	Input mux resistance (total equivalent sampling resistance)	1.5	2	2.5	KΩ
t_{CONV}	Conversion time (f_{ADC_CLK}=14 MHz)			1	µs
	Conversion time	13			ADC_CLK cycles
INL	Integral linearity error			±1	LSB
DNL	Differential linearity error			±1	LSB

4.9 Power-up sequence

It is recommended to power up the power supplies in the order shown in *Figure 6*.

V_{DD} 1.2 is brought up first, followed by V_{DD} 1.8, then V_{DD} 2.5 and finally V_{DD} 3.3. The minimum time (Δt) between each power up is >0 µs.

Figure 6. Power-up sequence



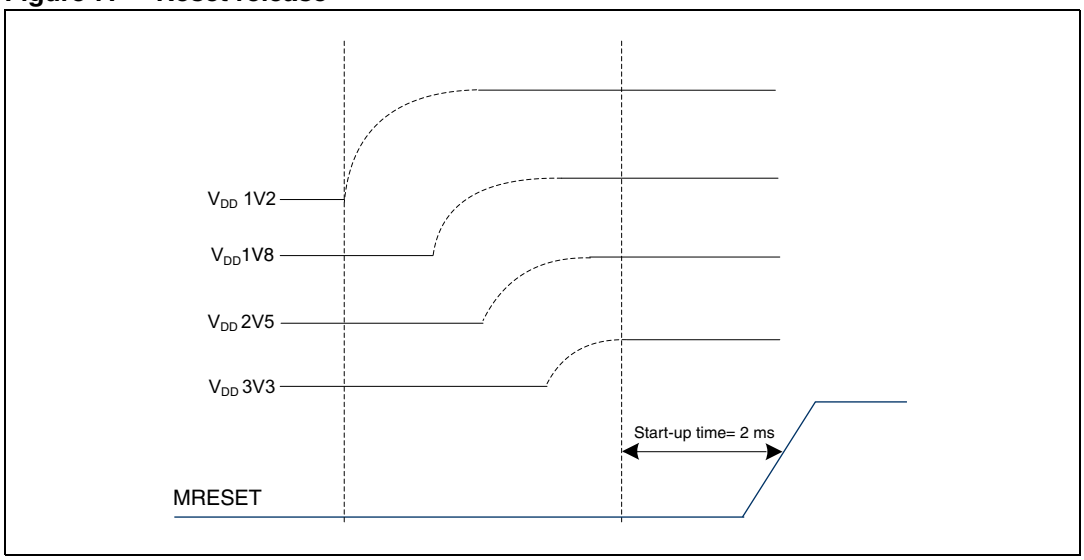
4.10 Power-down sequence

All power supplies can be shut down at the same time.

4.11 Reset release

The master reset (MRESET) must be released after all the power supplies are stable and for a time interval of 2 ms, which is the start-up time of the main oscillator.

Figure 7. Reset release



5 Timing requirements

This chapter provides the timing requirements for the synchronous and asynchronous IPs present in SPEAr320S.

The signal transition levels used for timing measurements are: 0.2*VDD and 0.8*VDD.

5.1 External interrupt timing characteristics

In legacy modes, all the interrupts are high-level triggered. In extended mode, interrupt trigger polarity is programmable as rising or falling edge.

Table 45. PL_GPIO external interrupt input timing

Symbol	Description	Min	Unit
tINT	Minimum width for rising edge interrupt pulse	24	ns

5.2 Reset timing characteristics

Table 46. Cold reset (at power-on)

Symbol	Description	Min	Unit
tRP	MRESET pin active low state duration	10	ms

Note: Warm reset is generated by writing any value to the system controller SYSSTAT register.

5.3 CLCD timing characteristics

The CLCD has a wide variety of configurations, and the parameters change accordingly.

The timing characterization is performed assuming an output load capacitance of 10 pF on all outputs.

Figure 8. CLCD waveform

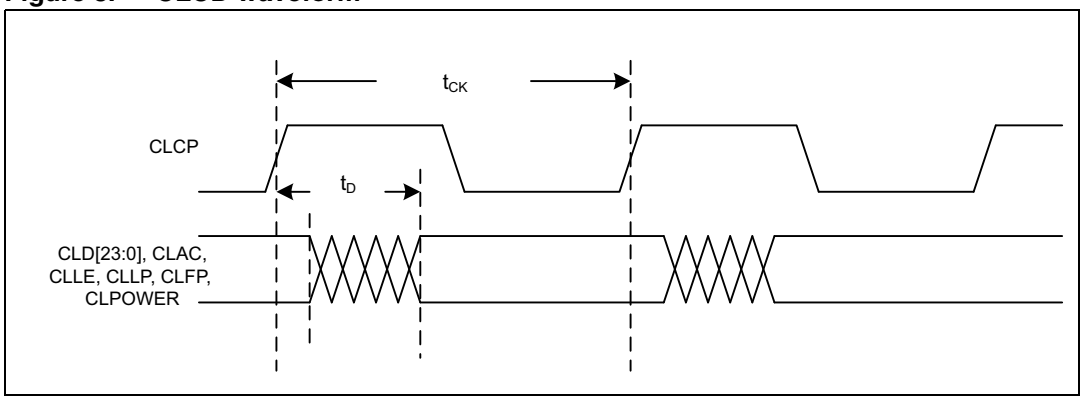


Table 47. CLCD timing requirements

Symbol	Description	Min	Max	Unit
t_{CK}	CLCP clock period	20.83	41.66	ns
t_D	CLCP to CLCD output data delay	1	9.5	

5.4 DDR2 timing characteristics

The timing parameters listed below are defined by the JEDEC Standard for DDR memories. DDR memories whose parameters are within the ranges defined in *Table 48*, *Table 49* and *Table 50* can be interfaced with SPEAr320S.

Read cycle timing apply to DQS and DQ input to SPEAr. Write cycle timings refer to DQS and DQ output to SPEAr.

The timing characterization is performed assuming an output load capacitance of 10 pF on all the DDR pads.

5.4.1 DDR2 read cycle timing characteristics

Figure 9. DDR2 read cycle waveform

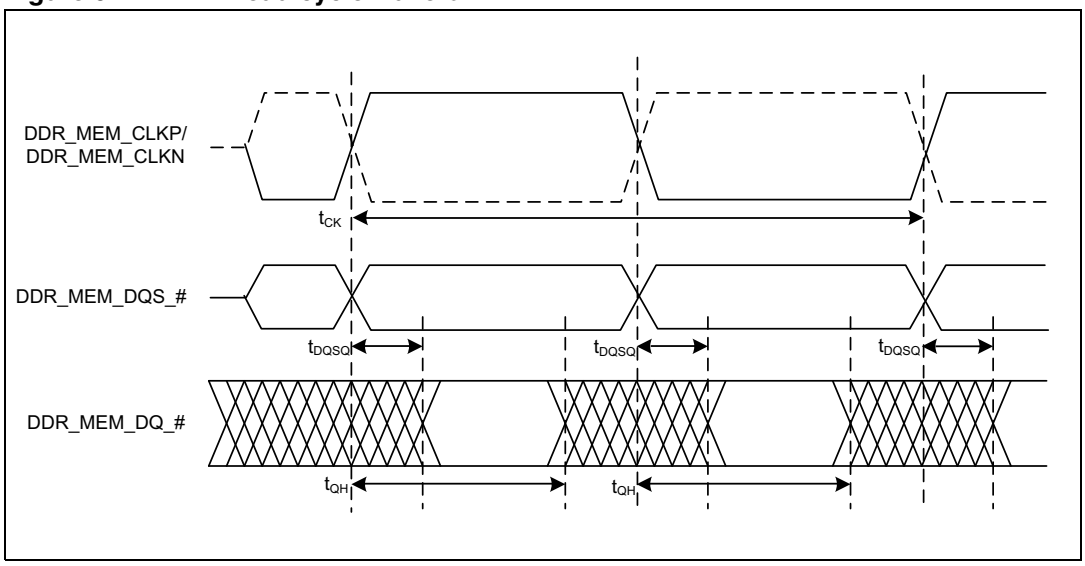


Table 48. DDR2 read cycle timing requirements

Symbol	Description	Min	Max	Unit
t_{CK}	DDR_MEM_CLKP/CLKN cycle time	3		ns
t_{DQSQ}	DQS to DQ input setup time	0	$0.25t_{CK}+0.4$	
t_{QH}	DQS to DQ input hold time	$0.25t_{CK}+0.7$	$0.5t_{CK}$	

5.4.2 DDR2 write cycle timing characteristics

Figure 10. DDR2 write cycle waveform

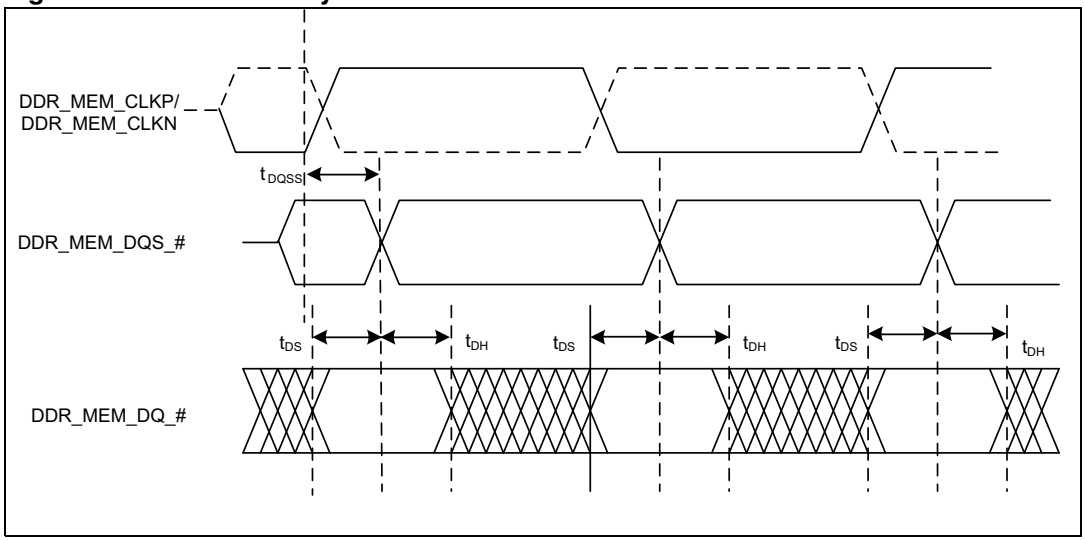


Table 49. DDR2 write cycle timing requirements

Symbol	Description	Min	Max	Unit
t_{DQSS}	Positive DQS latching edge to associated CK edge	-0.5	0.5	ns
t_{DS}	DQ & DQM output setup time relative to DQS	0	$0.25t_{CK} - 0.76$	
t_{DH}	DQ & DQM output hold time relative to DQS	0	$0.25t_{CK} - 0.84$	

5.4.3 DDR2 command timing characteristics

Figure 11. DDR2 command waveform

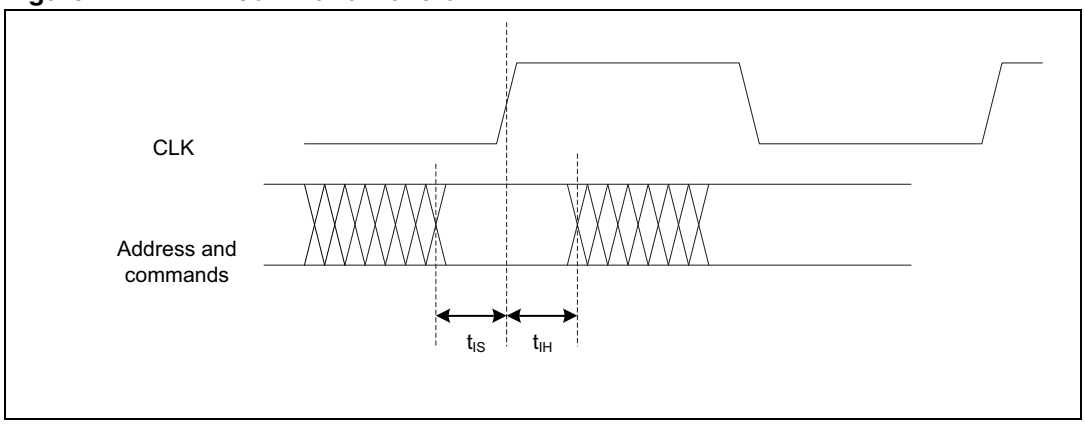
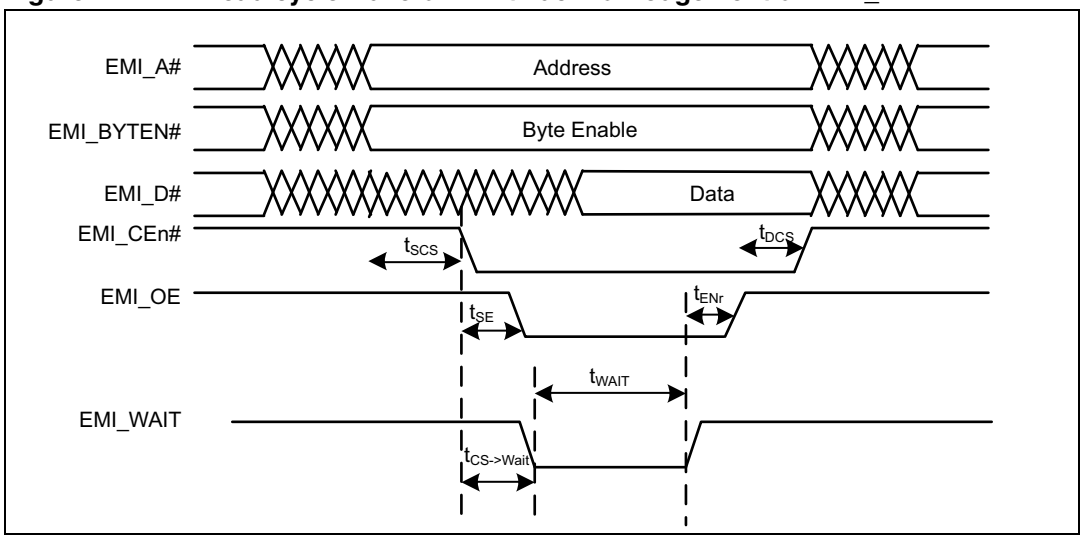


Table 50. DDR2 command timing requirements

Symbol	Description	Min	Max	Unit
t_{IS}	Address and control output setup time	0	$0.5t_{CK} - 0.5$	ns
t_{IH}	Address and control output hold time	0	$0.5t_{CK} - 0.59$	

5.5 EMI timing characteristics

Figure 12. EMI read cycle waveform with acknowledgement on EMI_WAIT



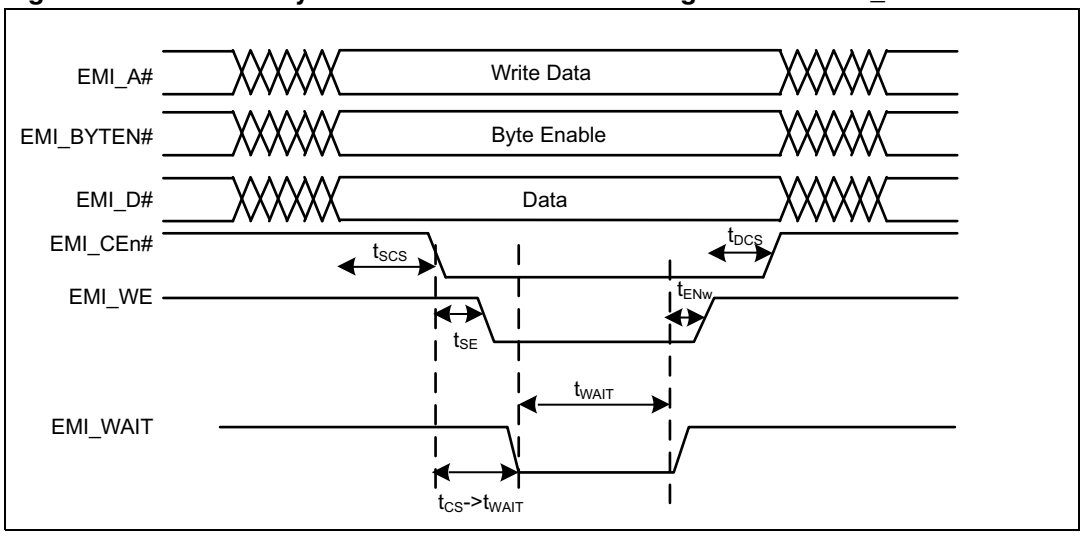
Note: The values of t_{SE}, t_{ENr}, t_{DCS}, t_{SCS} are programmable via the EMI registers.

Table 51. EMI timing requirements for read cycle with acknowledgement on WAIT

Symbol	Min
$t_{CS->Wait}$	t_{HCLK}
t_{WAIT}	$4*t_{HCLK}$

Note: Values in Table 51 refer to the common internal source clock which has a period of t_{HCLK} = 6 ns.

Figure 13. EMI write cycle waveform with acknowledgement on EMI_WAIT



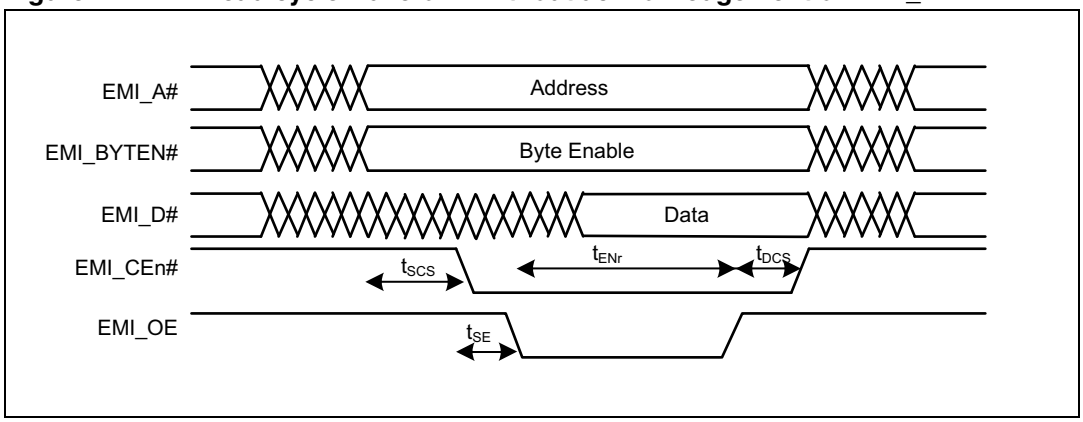
Note: The values of t_{SE}, t_{ENw}, t_{DCS}, t_{SCS} are programmable via the EMI registers.

Table 52. EMI timing requirements for write cycle with acknowledgement on WAIT

Symbol	Min
$t_{CS->Wait}$	t_{HCLK}
t_{WAIT}	$4*t_{HCLK}$

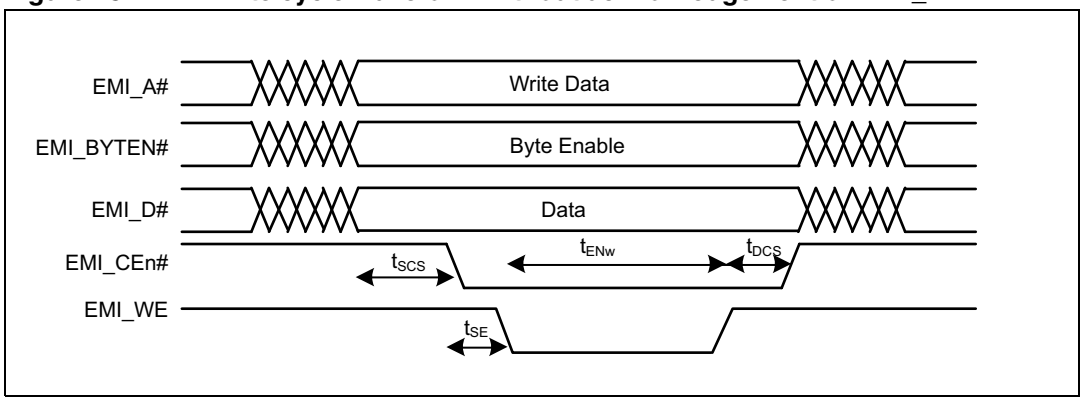
Note: Values in Table 52 refer to the common internal source clock which has a period of t_{HCLK} = 6 ns.

Figure 14. EMI read cycle waveform without acknowledgement on EMI_WAIT



Note: The values of t_{SE}, t_{ENr}, t_{DCS}, t_{SCS} are programmable via the EMI registers.

Figure 15. EMI write cycle waveform without acknowledgement on EMI_WAIT



Note: The values of t_{SE}, t_{ENw}, t_{DCS}, t_{SCS} are programmable via the EMI registers.

Table 53. EMI timing requirements

Direction	Signal name	Max	Min	Unit
Output	EMI_A0-EMI_A23	8.612293	1.93584	ns
	EMD0-EMID15	9.471291	2.260195	
	EMI_CE0	8.764648	2.90581	
	EMI_CE1	7.977348	2.636304	
	EMI_CE2	9.027624	2.930175	
	EMI_CE3	9.29631	3.006315	
	EMI_BYTEN0	9.554388	3.092855	
	EMI_BYTEN1	9.233592	3.038856	
	EMI_RE	8.193018	2.680564	
	EMI_WE	8.172619	2.80189	
Input	EMI_D0-EMI_D15	10.8188	1.30245	

5.6 Ethernet MII timing characteristics

The timing characterization is performed assuming an output load capacitance of 5 pF on the MII TX clock (MII#_TXCLK) and 10 pF on the other pads.

5.6.1 MII transmit timing characteristics

Figure 16. MII TX waveform

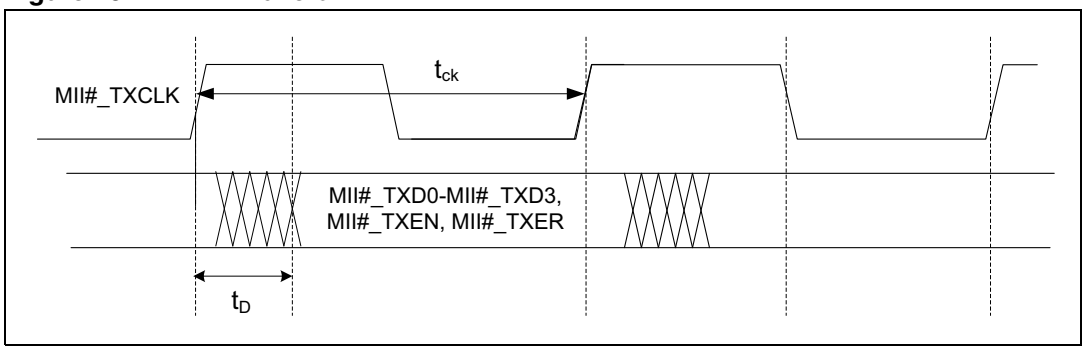


Table 54. MII TX timing requirements

Symbol	Description	Min	Max	Unit
t_{CK}	MII#_TXCLK clock period	40	40	ns
t_D	MII#_TXCLK to MII output data delay	3.34	11.86	

Note: To calculate the t_{SETUP} value for the PHY, you have to consider the next t_{CK} rising edge, so you have to apply the following formula: $t_{SETUP} = t_{CK} - t_{max}$

5.6.2 MII receive timing characteristics

Figure 17. MII RX waveform

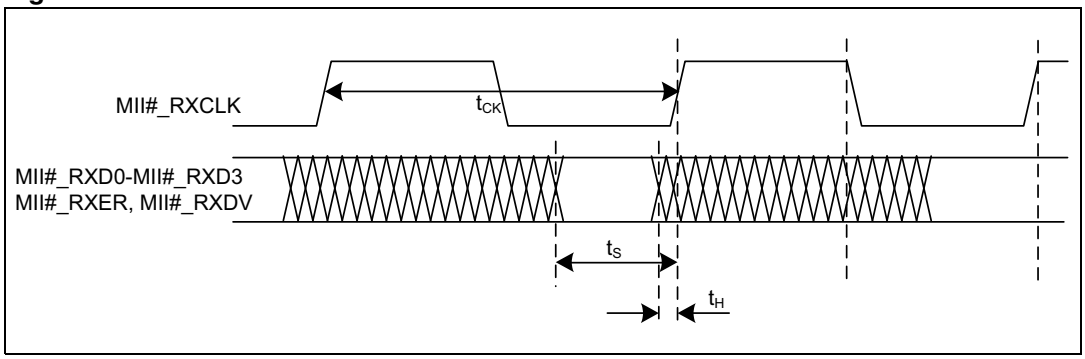


Table 55. MII RX timing requirements

Symbol	Description	Min	Max	Unit
t_{CK}	MII#_TXCLK clock period	40	40	ns
t_S	Setup time requirement for MII receive data	12.5		
t_H	Hold time requirement for MII receive data	-2		

5.6.3 MDIO timing characteristics

Figure 18. MDC waveform

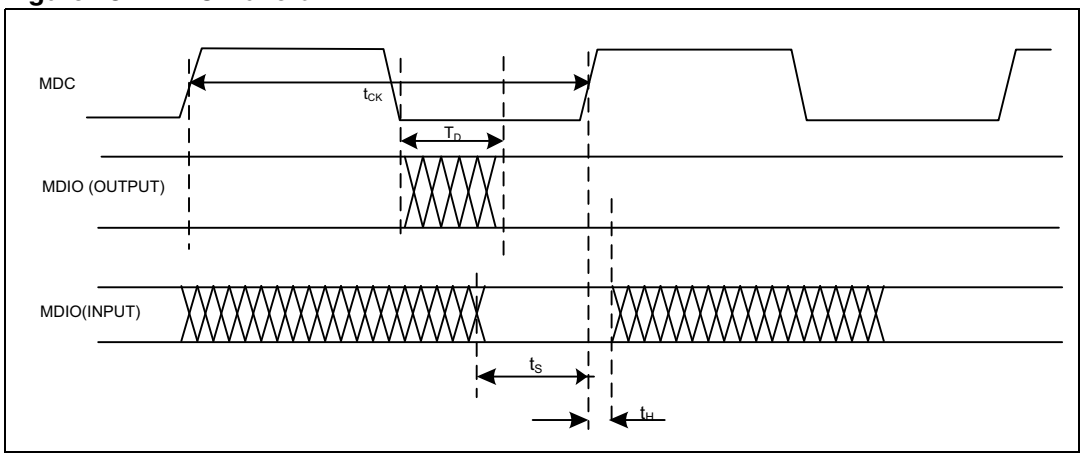


Table 56. MDC timing requirements

Symbol	Description	Min	Max	Unit
t_{CK}	MDC clock period	614.4	614.4	ns
t_D	Falling edge of MDC to MDIO output delay	204	0.64	
t_S	Setup time requirement for MDIO input	9.6		
t_H	Hold time requirement for MDIO input	-6.6		

Note: When MDIO is used as output the data are launched on the falling edge of the clock as shown in Figure 18.

5.7 Ethernet RMII timing characteristics

5.7.1 RMII transmit timing characteristics

Figure 19. RMII TX waveform

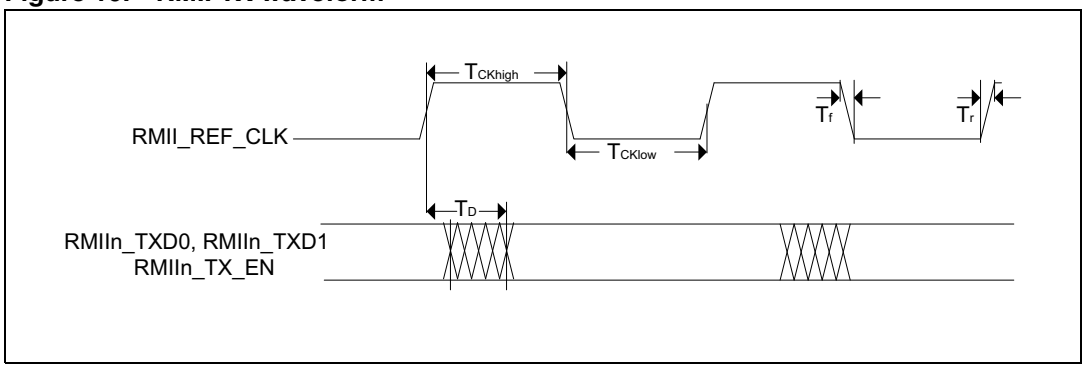


Table 57. RMII TX timing requirements

Symbol	Description	Min	Max	Unit
t_{CK}	RMII_REF_CLK period	20		ns
t_D	Clock to RMII0_TXD output delay	2.95	9.5	
	Clock to RMII1_TXD output delay	2.95	9.3	

5.7.2 RMII receive timing characteristics

Figure 20. RMII RX waveform

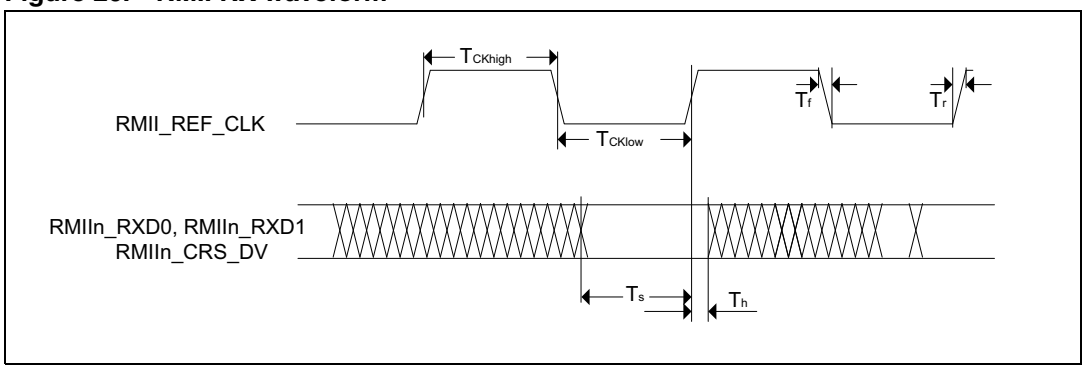


Table 58. RMII RX timing requirements

Symbol	Description	Min	Max	Unit
t_{CK}	RMII_REF_CLK period	20		ns
t_S	Setup time requirement for RMII0 receive data	4.9		
	Setup time requirement for RMII1 receive data	5		
t_H	Hold time requirement for RMII0 receive data	0.1		
	Hold time requirement for RMII1 receive data	-0.09		

5.8 FSMC timing characteristics

The FSMC present in SPEAr320S can interface external parallel NAND Flash memories.

The timing characterization is performed using primetime assuming an output load capacitance of 3 pF on the data, 15 pF on FSMC_CSx, FSMC_RE and FSMC_WE and 10 pF on FSMC_ADDR_LE and FSMC_CMD_LE.

Figure 21. Output command signal waveform

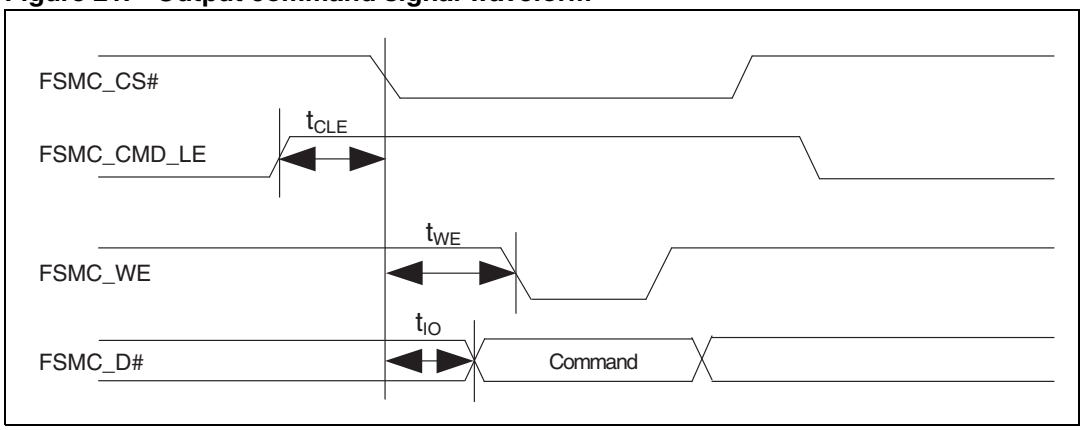


Figure 22. Output address signal waveform

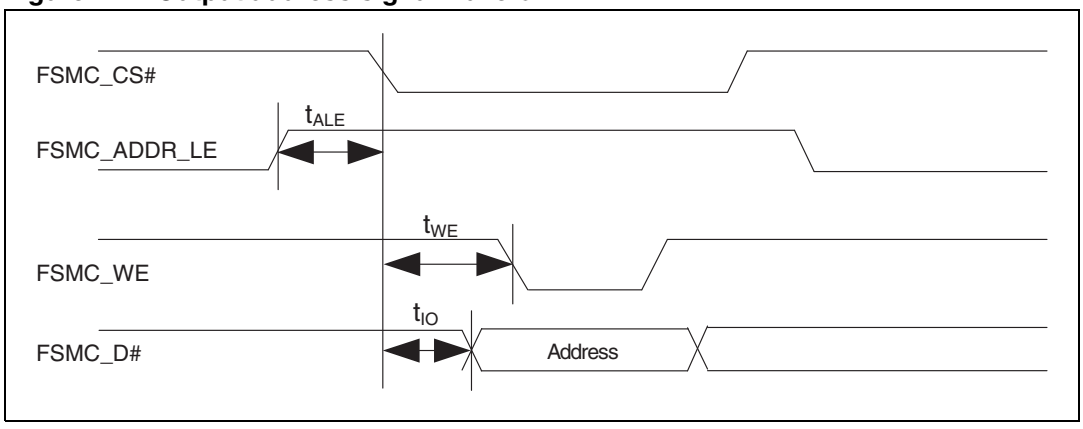


Figure 23. In/out data address signal waveform

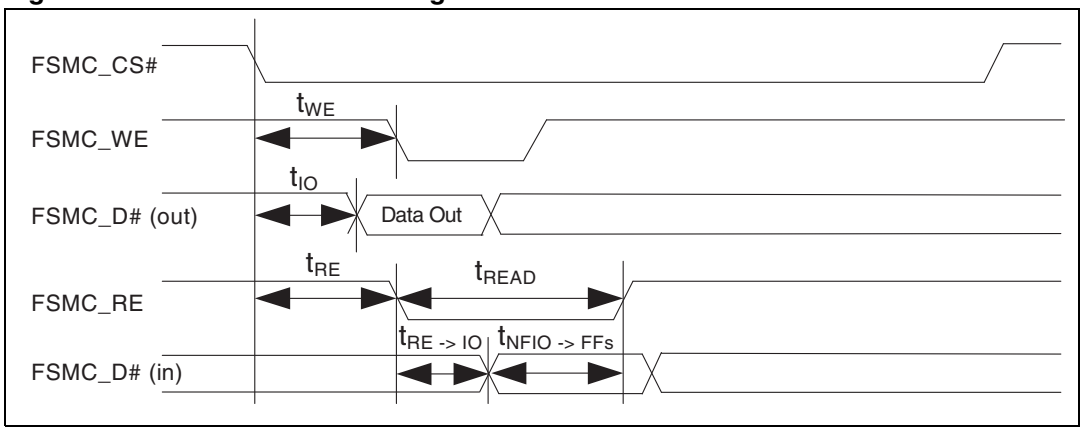


Table 59. FSMC timing requirements

Symbol	Min	Max
t_{CLE}	-3.9	2.8
t_{ALE}	-4.2	2.6
t_{WE}(1)	(((Tset+1) * t_{HCLK}) - 3 ns)	(((Tset+1) * t_{HCLK}) + 3 ns)
t_{RE}(1)	(((Tset+1) * t_{HCLK}) - 3 ns)	(((Tset+1) * t_{HCLK}) + 3 ns)
t_{IO}(2)	(((Thiz +1) * t_{HCLK}) - 3 ns)	(((Thiz +1) * t_{HCLK})+ 3 ns)
t_{READ}(3)	((Twait+1)* t_{HCLK}	

1. Programmable by the Tset bits in the FSMC registers.
2. Programmable by the Thiz bits in the FSMC registers.
3. Programmable by the Twait bits in the FSMC registers.

Note: Values in Table 59 refer to the common internal source clock which has a period of t_{HCLK} = 6 ns.

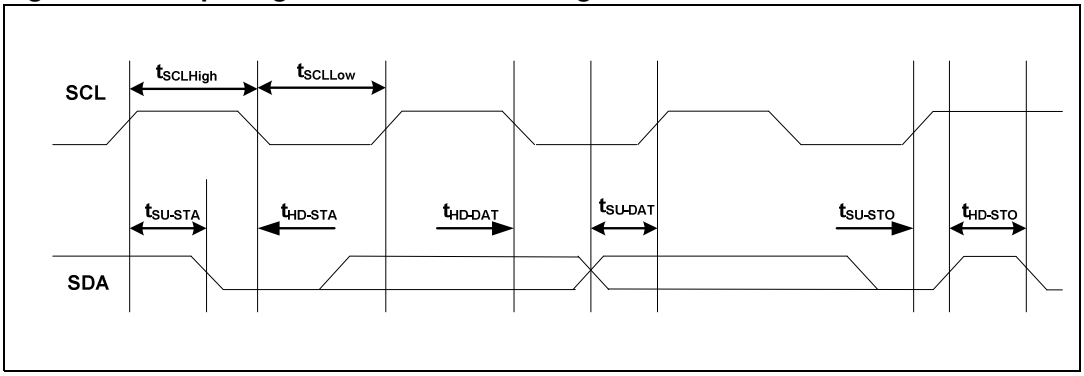
Table 60. FSMC signals timing requirements

Direction	Signal name	Max	Min	Data path width	Unit
Output	FSMC_CMD_LE	10.57	3.1		ns
	FSMC_ADDR_LE	9.5	2.8		
	FSMC_WE	8.5	2.9		
	FSMC_RE	8.4	2.75		
	FSMC_CS0	9.165836	3.07661		
	FSMC_CS1	8.473722	2.81431		
	FSMC_CS2	9.172739	3.02958		
	FSMC_CS3	9.808426	3.21934		
	FSMC_D7-FSMC_D0	7.710164	2.298715	8-bit	
	FSMC_D15-FSMC_D8	9.301547	2.420165	8-bit	
	FSMC_D15-FSMC_D0	9.301547	2.298715	16-bit	
Input	FSMC_RDY/BUSY	6.88	1.7		
	FSMC_D7-FSMC_D0	8.8809	1.18356	8-bit	
	FSMC_D15-FSMC_D8	10.875302	1.37802	8-bit	
	FSMC_D15-FSMC_D0	10.875302	1.18356	16-bit	

5.9 I²C timing characteristics

The timing characterization is performed using primetime assuming an output load capacitance of 10 pF on SCL and SDA.

Figure 24. Output signal waveform for I²C signals



The timings of the high and low level of SCL ($t_{SCLHigh}$ and t_{SCLLow}) are programmable.

The clock-to-output data delay is:

- MIN (T(clk+data)min) = 5.9
- MAX (T(clk+data)max) = 15

The timings shown in *Figure 24* depend on the programmed value of $t_{SCLHigh}$ and t_{SCLLow}. The values listed in *Table 61* to *Table 63* have been calculated using the minimum programmable values of :

- High-speed mode: IC_HS_SCL_HCNT= 19 and IC_HS_SCL_LCNT= 53 registers
- Fast-speed mode: IC_FS_SCL_HCNT= 99 and IC_FS_SCL_LCNT= 215 registers
- Standard-speed mode: IC_SS_SCL_HCNT= 664 and IC_SS_SCL_LCNT= 780 registers

These minimum values depend on the AHB clock frequency, which is 166 MHz.

Table 61. I²C timing requirements in high-speed mode

Parameter	Min	Unit
t_{SU-STA}	140	ns
t_{HD-STA}	325	
t_{SU-DAT}	300	
t_{HD-DAT}	1	
t_{SU-STO}	620	
t_{HD-STO}	4745	

Table 62. I^2C timing requirements in fast-speed mode

Parameter	Min	Unit
t_{SU-STA}	620	ns
t_{HD-STA}	602	
t_{SU-DAT}	1270	
t_{HD-DAT}	1	
t_{SU-STO}	620	
t_{HD-STO}	4745	

Table 63. I^2C timing requirements in standard-speed mode

Parameter	Min	Unit
t_{SU-STA}	4718	ns
t_{HD-STA}	3992	
t_{SU-DAT}	4660	
t_{HD-DAT}	1	
t_{SU-STO}	4010	
t_{HD-STO}	4745	

5.10 I2S timing characteristics

Figure 25. I2S waveform

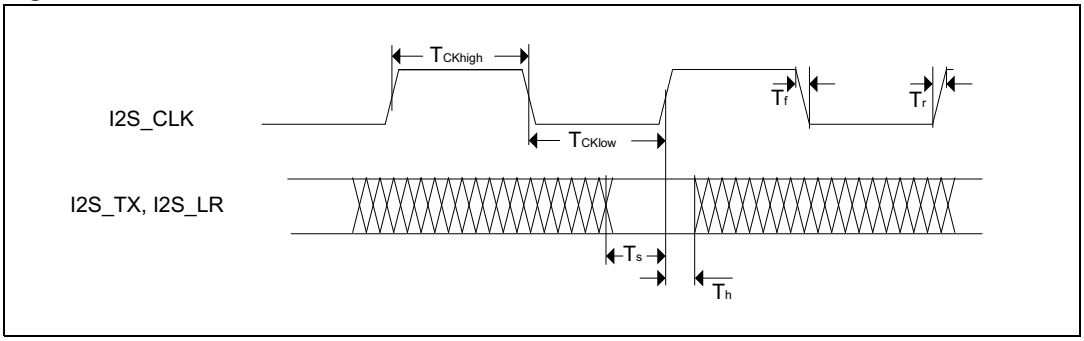


Table 64. I2S timing requirements

Symbol	Description	Min	Max	Unit
t_{CK}	I2S_CLK clock period	40		ns
t_D	I2S_CLK to I2S_TX output delay	3.8	9	
t_S	Setup time requirement for I2S_CLK	6		
t_H	Hold time requirement for I2S_CLK	1		

5.11 SD timing characteristics

Figure 26. SD timing waveform

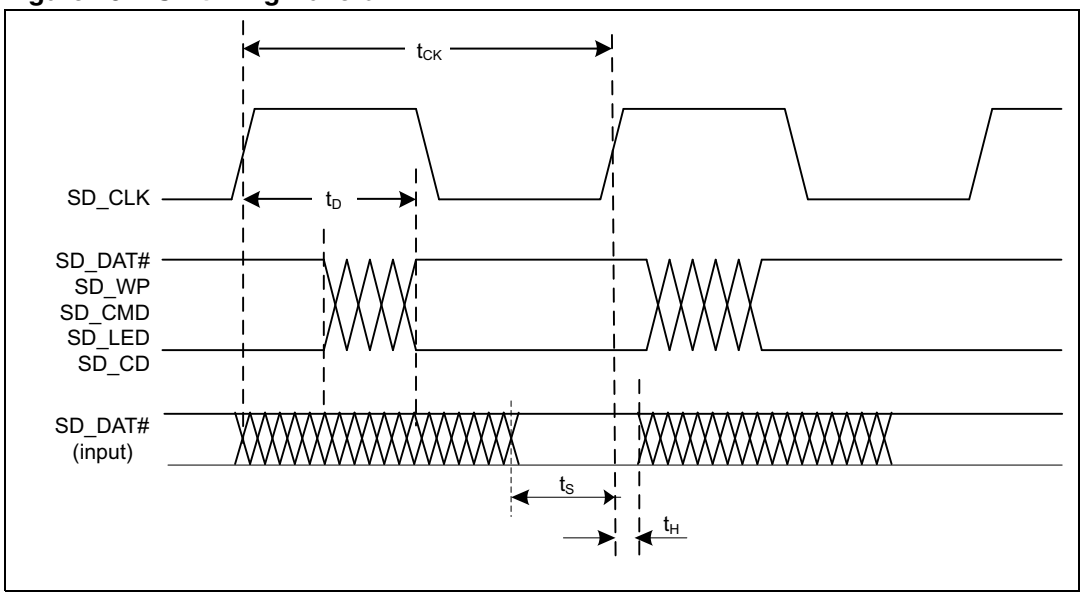


Table 65. SD timing requirements (high-speed mode, 48 MHz)

Symbol	Description	Min	Max	Unit
t_{CK}	SD_CLK clock period	20.8	–	ns
t_D	SD_CLK to SD output delay	-1.60	10	
t_S	Setup time requirement for SD inputs	7.35		
t_H	Hold time requirement for SD inputs	0.19		

Table 66. SD timing requirements (full-speed mode, 24 MHz)

Symbol	Description	Min	Max	Unit
t_{CK}	SD_CLK clock period	41.6	–	ns
$t_{ck\text{-}half}$	SD_CLK half period	20.8		
t_D	SD_CLK to SD output delay	-0.40	10	
t_S	Setup time requirement for SD inputs	7.35		
t_H	Hold time requirement for SD inputs	0.19		

Note: In full-speed mode, the frequency is 24 MHZ (41.6 ns). The data is launched at the falling edge of the 24 MHZ clock and captured on the clock's rising edge (the effective available time is always 20.8 ns)

5.12 SMI timing characteristics

Figure 27. SMI input/output waveform

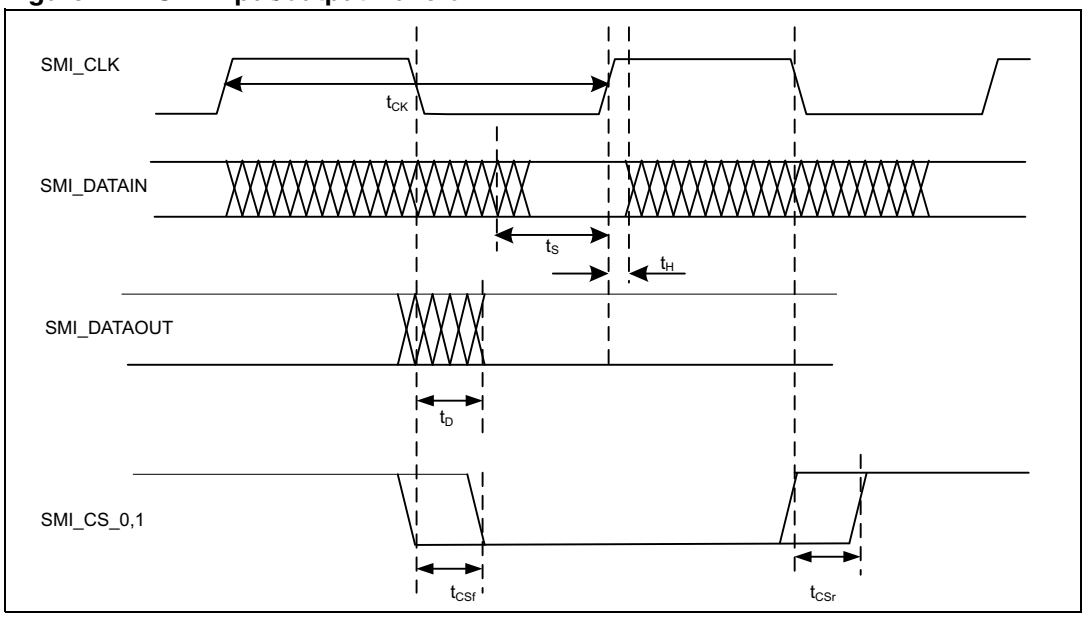


Table 67. SMI timing requirements

Symbol	Description	Min	Max	Unit
t_{CK}	SMI clock period	20	50	ns
t_D	SMI_CLK to SMI_DATAOUT output delay	-2.96	3.05	
t_S	Setup requirement for SMI_DATAIN	8.05		
t_H	Hold requirement for SMI_DATAIN	-2.53		
t_{CSf}	Minimum and maximum delay of falling edge of SMI_CS_0 , 1 with regard to SMI_CLK	-3.0	2.9	
t_{CSr}	Minimum and maximum delay of rising edge of SMI_CS_0 , 1 with regard to SMI_CLK	-2.8	2.8	

5.13 SSP timing characteristics

This module provides a programmable length shift register which allows serial communication with other SSP devices through a 3- or 4-wire interface (SSP#_CLK, SSP#_MISO, SSP#_MOSI and SSP#_CSn), where x= 0 to 2 and n= 1 to 4.

The SSP supports the following features related to timings:

- Master/Slave mode operation
- Chip-selects for interfacing multiple slave SPI devices.
- 3 or 4 wire interface (SSP_SCK, SSP_MISO, SSP_MOSI and SSP_CSn)
- Single interrupt
- Separate DMA events for SPI receive and transmit
- 16-bit shift register
- Receive buffer register
- Programmable character length (2 to 16 bits)
- Programmable SSP clock frequency range
- 8-bit clock pre-scaler
- Programmable clock phase (delay or no delay)
- Programmable clock polarity (CPOL)

Note: The following tables and figures show the characterization of the SSP using the SPI protocol.

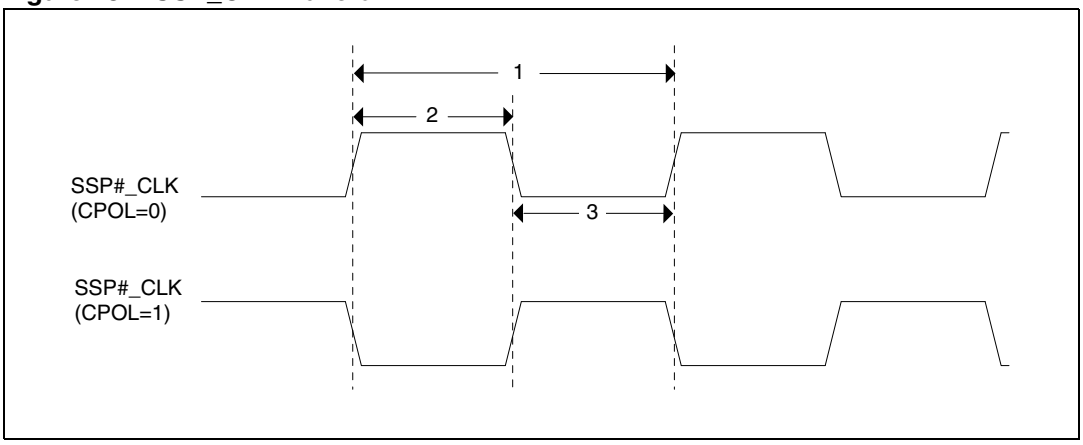
Table 68. SSP timing requirements (all modes)

No.(1)	Parameters		Min	Max	Unit
1	$T_{c(CLK)}$	Cycle time, SSP#_CLK	24	–	ns
2	$T_{w(CLKH)}$	Pulse duration, SSP#_CLK high	0.49*To	0.51*To	
3	$T_{w(CLKL)}$	Pulse duration, SSP#_CLK low	0.49*To	0.51*To	

1. The number used in the graphics to represent the corresponding parameter.

T = Tc(CLK) = SSP#_CLK period is equal to the SSP module master clock divided by a configurable divider.

Figure 28. SSP_CLK waveform



5.13.1 SPI master mode timing characteristics (clock phase = 0)

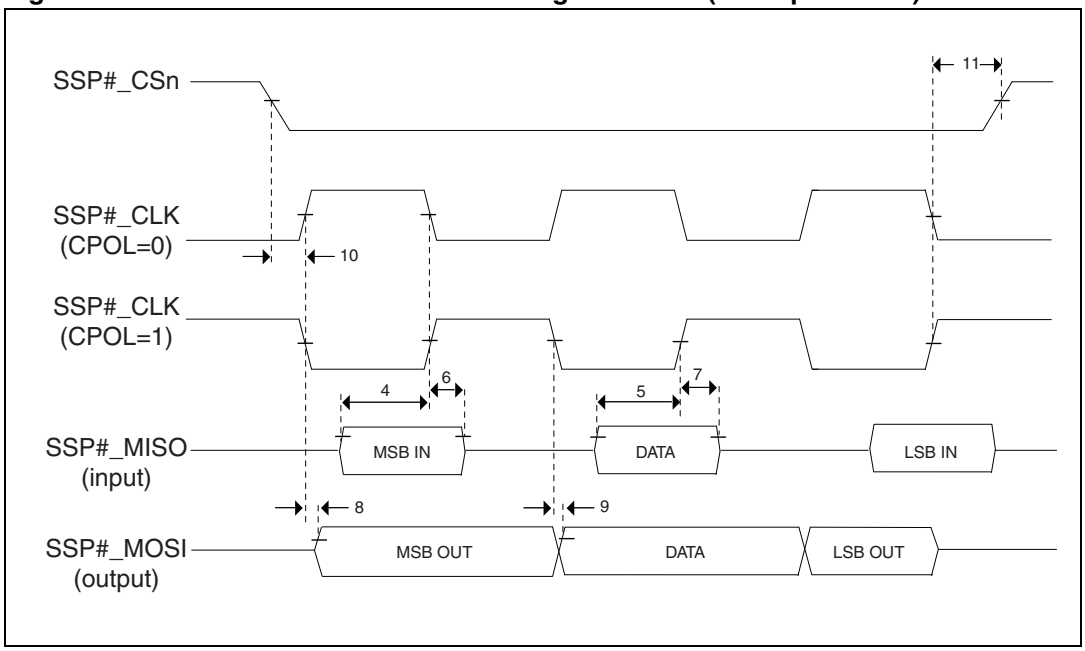
Table 69. SPI master mode timing requirements (clock phase = 0)

No.	Parameters			Min	Max	Unit
4	$t_{su(DIV-CLKL)}$	Setup time, MISO (input) valid before SSP#_CLK (output) falling edge	CPOL = 0	–	7.8	ns
5	$t_{su(DIV-CLKH)}$	Setup time, MISO (input) valid before SSP#_CLK (output) rising edge	CPOL = 1	–	7.8	
6	$t_{h(CLKL-DIV)}$	Hold time, MISO (input) valid after SSP#_CLK (output) falling edge	CPOL = 0	-2.7	–	
7	$t_{h(CLKH-DIV)}$	Hold time, MISO (input) valid after SSP#_CLK (output) rising edge	CPOL = 1	-2.7	–	

Table 70. Switching characteristics over recommended operating conditions for SPI master mode (clock phase =0)

No.	Parameters			Min	Max	Unit
8	$t_{d(CLKH-DOV)}$	Delay time, SSP#_CLK (output) rising edge to MOSI (output) transition	CPOL = 0	2.7	9.4	ns
9	$t_{d(CLKL-DOV)}$	Delay time, SSP#_CLK (output) falling edge to MOSI (output) transition	CPOL = 1	2.7	9.4	
10	$t_{d(ENL-CLKH/L)}$	Delay time, SSP#_CSn (output) falling edge to first SSP#_CLK (output) rising or falling edge		T		
11	$t_{d(CLKH/L-ENH)}$	Delay time, SSP#_CLK (output) rising or falling edge to SSP#_CSn (output) rising edge		3	10	

Figure 29. SPI master mode external timing waveform (clock phase = 0)



5.13.2 SPI master mode timing characteristics (clock phase = 1)

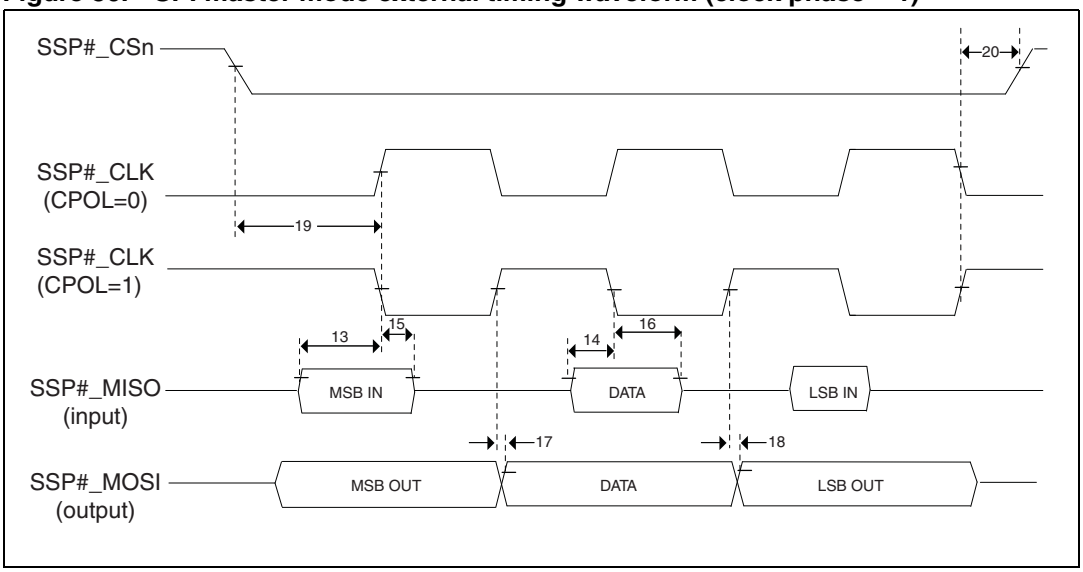
Table 71. SPI master mode timing requirements (clock phase = 1)

No.	Parameters			Min	Max	Unit
13	$t_{su(DIV-CLKL)}$	Setup time, MISO (input) valid before SSP#_CLK (output) rising edge	CPOL = 0	–	7.8	ns
14	$t_{su(DIV-CLKH)}$	Setup time, MISO (input) valid before SSP#_CLK (output) falling edge	CPOL = 1	–	7.8	
15	$t_{h(CLKL-DIV)}$	Hold time, MISO (input) valid after SSP#_CLK (output) rising edge	CPOL = 0	-2.7	–	
16	$t_{h(CLKH-DIV)}$	Hold time, MISO (input) valid after SSP#_CLK (output) falling edge	CPOL = 1	-2.7	–	

Table 72. Switching characteristics over recommended operating conditions for SPI master mode (clock phase = 1)

No.	Parameters			Min	Max	Unit
17	$t_{d(CLKH-DOV)}$	Delay time, SSP#_CLK (output) falling edge to MOSI (output) transition	CPOL = 0	2.7	9.5	ns
18	$t_{d(CLKL-DOV)}$	Delay time, SSP#_CLK (output) rising edge to MOSI (output) transition	CPOL = 1	2.7	9.5	
19	$t_{d(ENL-CLKH/L)}$	Delay time, SSP#_CSn (output) falling edge to first SSP#_CLK (output) rising or falling edge		T/2		
20	$t_{d(CLKH/L-ENH)}$	Delay time, SSP#_CLK (output) rising or falling edge to SSP#_CSn (output) rising edge		3	10	

Figure 30. SPI master mode external timing waveform (clock phase = 1)



5.14 UART timing characteristics

No timing characterization has been performed for the UART. For information related to baud rate generation, refer to:

- *Section 2.12: Asynchronous serial ports (UART)*
- *RM0321, Reference manual, SPEAr320S address map and registers*

6 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK® is an ST trademark.

Table 73. LFBGA289 (15 x 15 x 1.7 mm) mechanical data

Dim.	mm			inches		
	Min.	Type	Max.	Min.	Type	Max.
A			1.700			0.0669
A1	0.270			0.0106		
A2		0.985			0.0387	
A3		0.200			0.0078	
A4			0.800			0.0315
b	0.450	0.500	0.550	0.0177	0.0197	0.0217
D	14.850	15.000	15.150	0.5846	0.5906	0.5965
D1		12.800			0.5039	
E	14.850	15.000	15.150	0.5846	0.5906	0.5965
E1		12.800			0.5039	
e		0.800			0.0315	
F		1.100			0.0433	
ddd			0.200			0.0078
eee			0.150			0.0059
fff			0.080			0.0031

Figure 31. LFBGA289 package dimensions

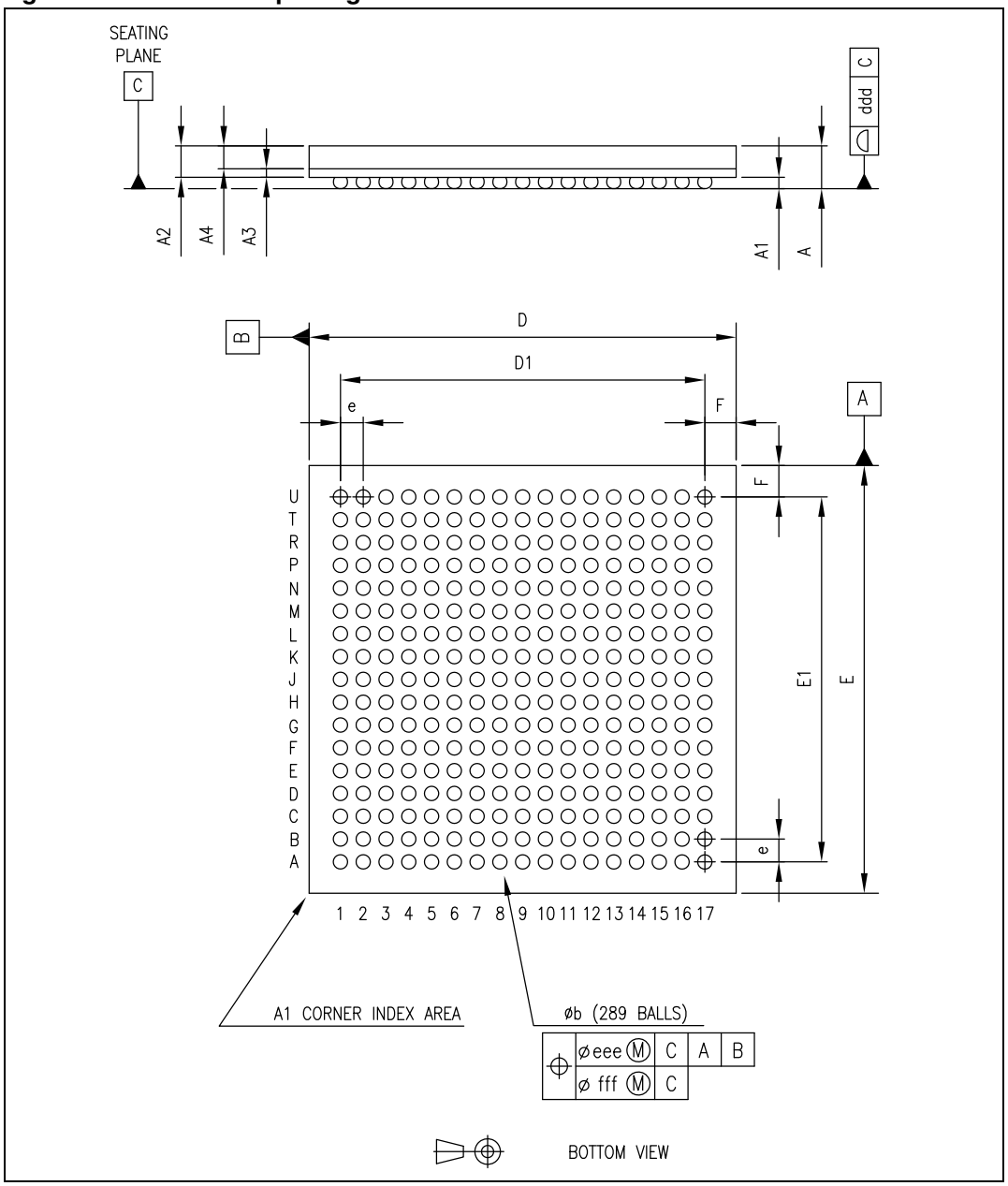


Table 74. Thermal resistance characteristics

Package	Θ_{JC} (°C/W)	Θ_{JB} (°C/W)	Θ_{JA}(°C/W)(1)
LFBGA289	18.5	24.5	33

1. Measured on JESD51 2s2p test board.

Appendix A Acronyms

Table 75. List of acronyms

Acronym	Definition
ADC	Analog-to-digital converter
AES	Advanced encryption standard
AHB	AMBA high speed bus
AMBA	Advanced microcontroller bus architecture
APB	Advanced peripheral bus
BIST	Built-In self test
CAN	Controller area network
CBC	Cipher block chaining
CMOS	Complimentary metal-oxide semiconductor
CPU	Central processing unit
CRC	Cyclic redundancy check
DDR	Double data rate
DES	Data encryption standard
DLL	Delay locked loop (when applied to DDR memories)
DMA	Direct memory access
EMI	External memory interface
ETM	Embedded trace macrocell
FIFO	First-in-first-out
FIQ	Fast interrupt request
FPGA	Field programmable gate array
FSMC	Flexible static memory controller
GB	Giga bytes
GPIO	General purpose input / output
HLOS	High-level operating system
HMI	Human machine interface
HW	Hardware
IrDA	Infrared data association
IRQ	Interrupt request
JPEG	Joint photographic experts group
JTAG	Joint test action group
KB	Kilo bytes
LCD	Liquid color display

Table 75. List of acronyms (continued)

Acronym	Definition
LSB	Least significant bit
MAC	Media access control
MB	Mega bytes
MCU	Microcontroller unit
MD5	Message digest 5
MII	Media independent interface
MMU	Memory management unit
MSB	Most significant bit
PHY	Physical (device, transceiver, layer)
PLL	Phase locked loop
PWM	Pulse width modulation
RAM	Random access memory
RAS	Reconfigurable array subsystem
RF	Radio frequency
RFU	Reserved for future use
RISC	Reduced instruction set computing
RMII	Reduced media independent interface
ROM	Read only memory
RTC	Real-time clock
RTOS	Real-time operating system
RX	Receive
SHA-1	Secure hash algorithm
SMI	Serial memory interface
SoC	System-on-chip
SPI	Serial peripheral interface
SPP	Standard parallel port
SRAM	Static RAM
SSP	Synchronous serial port
SW	Software
TCM	Tightly coupled memory
TFT	Thin film transistor, a display technology
TX	Transmit
UART	Universal asynchronous receiver transmitter
USB	Universal serial bus

Table 75. List of acronyms (continued)

Acronym	Definition
VIC	Vectored interrupt controller
WDT	Watchdog timer

Revision history

Table 76. Document revision history

Date	Revision	Changes
5-Apr-2012	1	Initial release.

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